



说明

该参考设计实现了一个具有可调输出电压的 10A、两相升压转换器，该转换器可针对 16V 至 40V 直流电的电压进行动态设置。该输出电压范围允许跟踪由 PWM 信号或电压提供的音频信号。

资源

TIDA-01610
LM25122-Q1

设计文件夹
产品文件夹

特性

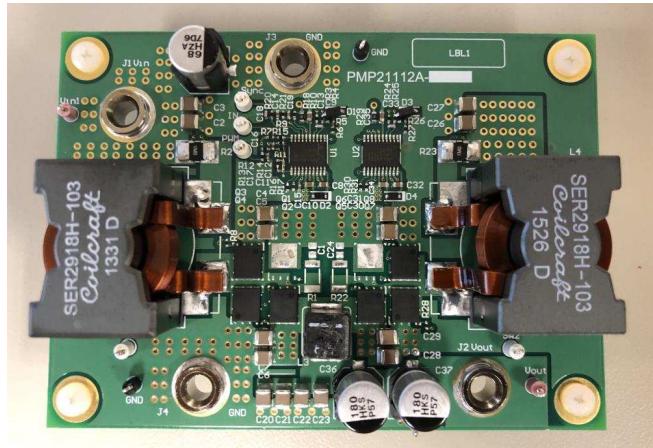
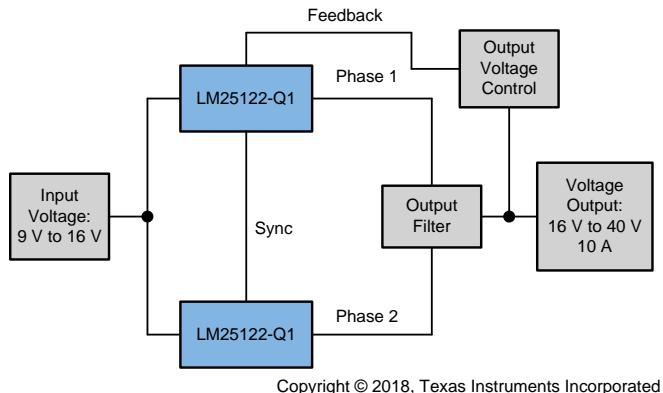
- 输入电压范围: 9V 至 16V
- 输出电压范围: 16V 至 40V
- 10A 持续输出电流
- 输出电压的 PWM 或直流控制
- 允许调节音频放大器电源以匹配信号条件

应用

- 汽车外部放大器



咨询我们的 E2E™ 专家



该 TI 参考设计末尾的重要声明表述了授权使用、知识产权问题和其他重要的免责声明和信息。

1 System Description

This reference design is a dual-phase boost using the LM25112-Q1 boost controller for automotive audio applications. This design can operate from 9 V to 16 V. The design has an adjustable output of 16 V to 40 V and is capable of sourcing a 10-A continuous current, suitable for powering a power audio amplifier. The LM25112-Q1 boost controller has a bypass function. When V_{IN} is equal to or greater than the set output voltage, the device will bypass V_{IN} using the high-side sync FET. Output adjustment is achieved by applying a 3.3-V PWM signal to the adjustment input. Adjusting the duty cycle of the PWM signal from 10% to 90% adjusts the output from 40 V to 16 V, respectively.

This design is also capable of tracking a sine wave up to 500 Hz without distortion and achieves a delay time of less than 300 μ s between sine wave and the output voltage. The switching frequency is set to 150 kHz and a four-layer PCB is used. When used with an audio processor system capable of supplying the PWM signal, the reference design can be used to track an audio signal, adjusting the output voltage based on the audio signal conditions. An audio amplifier powered by this circuit can provide high-power output when the boost output voltage is set high. A lower power supply voltage is used when less volume is required, allowing the audio amplifier to dissipate less heat than it would if the boost supply was left set to the maximum voltage.

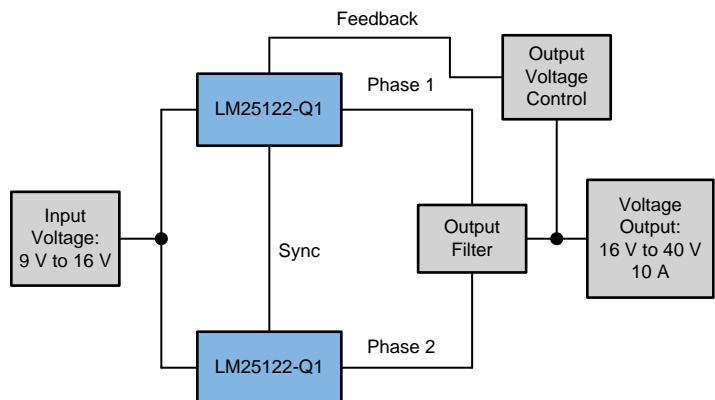
1.1 Key System Specifications

表 1. Key System Specifications

PARAMETER	SPECIFICATIONS
Input voltage	9-V to 16-V DC
Output voltage	16-V to 40-V DC
Output current	10 A
Tracking input voltage	0 V min, 3.3 V max 0.33 V to 3 V to meet output voltage range
Tracking input frequency	500 Hz, max
Tracking PWM frequency	100 kHz, minimum

2 System Overview

2.1 Block Diagram



Copyright © 2018, Texas Instruments Incorporated

图 1. TIDA-01610 Block Diagram

2.2 Highlighted Products

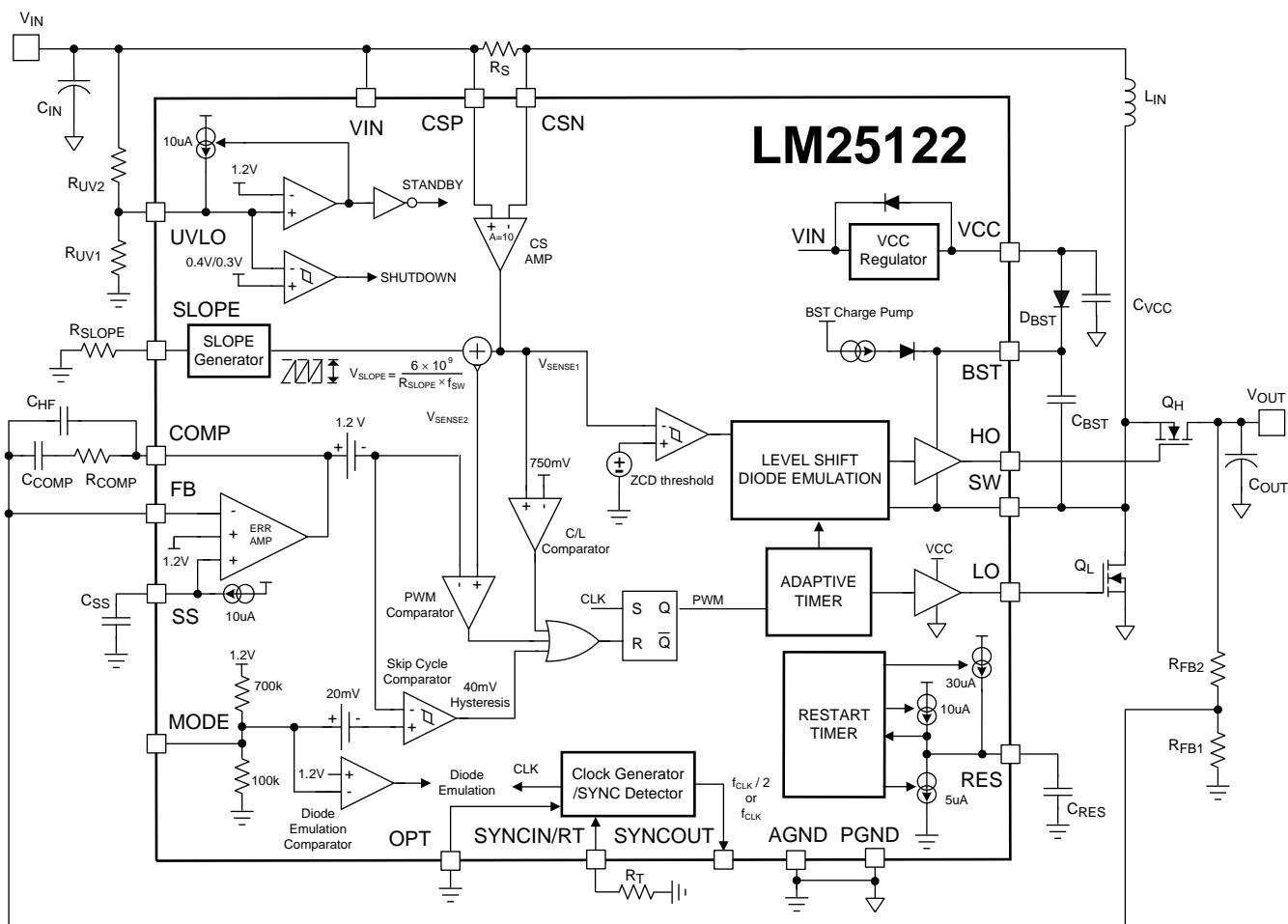
2.2.1 LM25122-Q1 Wide-Input Synchronous Boost Controller With Multiple Phase Capability

The LM25122 is a multiphase capable synchronous boost controller intended for high-efficiency synchronous boost regulator applications. The control method is based upon peak current mode control.

Current mode control provides inherent line feedforward, cycle-by-cycle current limiting and ease of loop compensation.

The switching frequency is programmable up to 600 kHz. Higher efficiency is achieved by two robust N-channel MOSFET gate drivers with adaptive dead-time control. A user-selectable diode emulation mode also enables discontinuous mode operation for improved efficiency at light load conditions.

An internal charge pump allows 100% duty cycle for high-side synchronous switch (bypass operation). A 180° phase shifted clock output enables easy multiphase interleaved configuration. Additional features include thermal shutdown, frequency synchronization, hiccup mode current limit and adjustable line undervoltage lockout.



Copyright © 2016, Texas Instruments Incorporated

图 2. LM25122-Q1 Block Diagram

2.3 System Design Theory

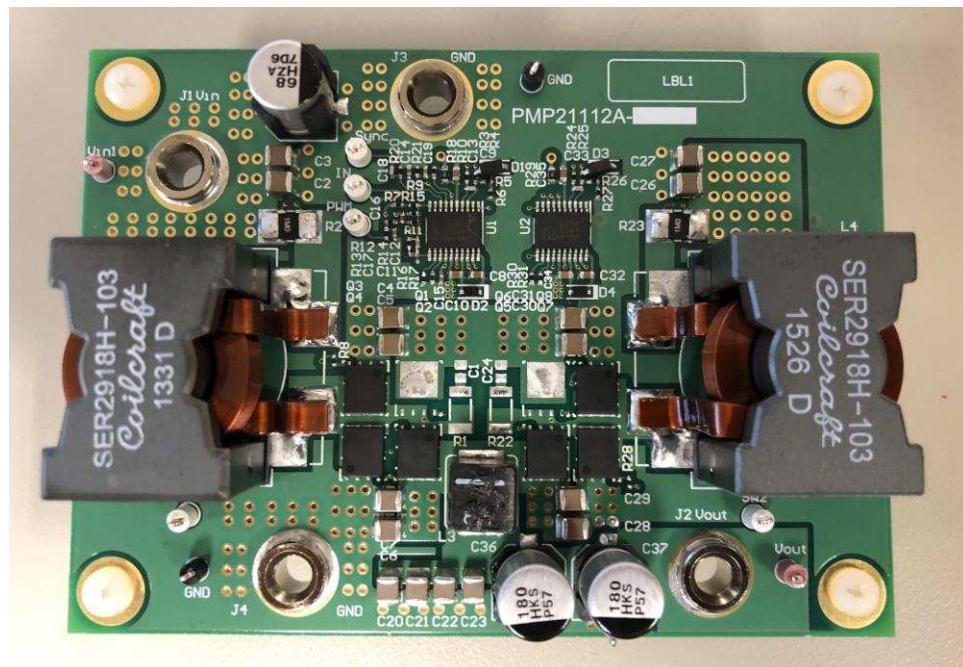
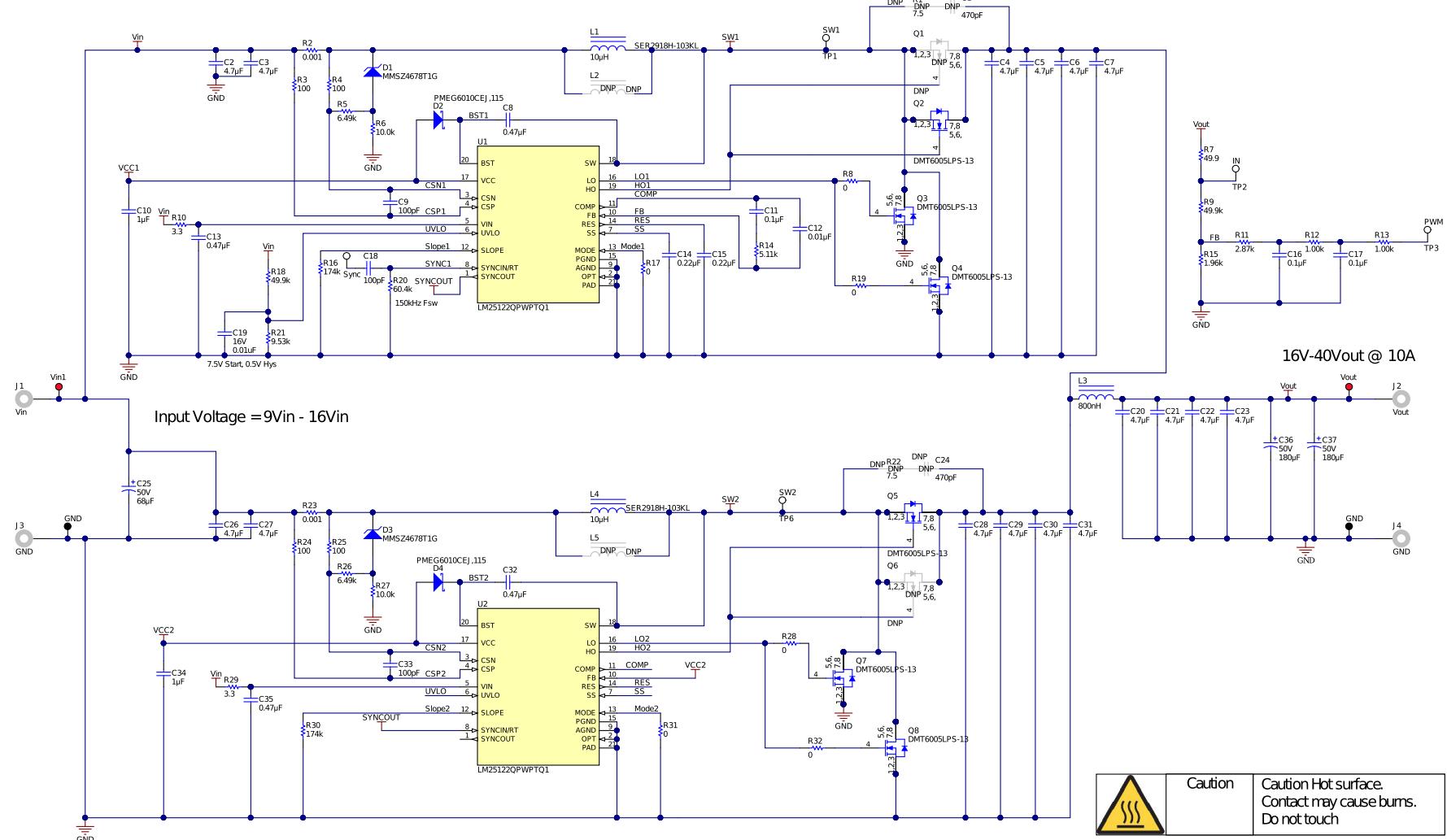


图 3. PCB Top View

2.3.1 Boost Design



Copyright © 2017, Texas Instruments Incorporated

图 4. TIDA-01610 Schematic

To ensure a continuous 10-A delivery to the load, a two-phase boost topology is used for this reference design. A two-phase implementation allows reduction in the size of filter capacitors and inductors while simultaneously lowering power dissipation in the main boost switch transistor. The filter inductor can shrink because the average current is divided between two inductors. The LM25122-Q1 is ideal for this design because it provides SYNCOUT and SYNC pins for use in creating multi-phase designs. In the reference design, U1 provides the master timing to U2. The feedback pin on U2 is tied to U2's VCC input to set the device for slave operation. Other than the interconnection for synchronization, the circuits around U1 and U2 are identical. The undervoltage lockout (UVLO) and compensation network are shared by the two boost circuits.

Each phase is designed as a 5-A output boost. The designer must make trade-offs because the voltage can be set anywhere in the range of 16 V to 40 V. The same constraints apply to both phases.

The switching frequency is set for 150 kHz by R20. The frequency setting and load requirements determine the necessary filter component values for inductance and total capacitance. 150 kHz is chosen to ensure minimum switching losses and heat dissipation. The value of inductors L1 and L4 is 10 μ H. The peak inductor current is almost 26 A, so the inductor must have a high current rating. Large inductor ripple current results in large core loss in the inductor. The selected inductance provides a 20% to 30% inductor ripple current ratio to the average inductor current across entire input and output operating voltages with a 10-A load current. The selected SER2918H-103 is suitable for high-power applications like this design.

The SER2918H-103 has DCR to reduce DC loss. Its core design reduces core loss.

Ceramic capacitors are chosen for the input and output filters closest to U1. C25, C2, C3, C26, and C27 are the input capacitors. The input capacitors in a boost topology see continuous current. Therefore, the input capacitor's RMS current is low. The worst case RMS current in the input capacitors is 2.6 A, so a single electrolytic capacitor with moderate ESR in addition to four ceramic capacitors ensures proper RMS current split as well as damping some amount of wiring inductance from the supply. C25 is shared by both boost phases.

The output capacitors in a boost topology see discontinuous, pulsating current. The worst case RMS current in the output capacitor is 20 A. One job of the output capacitors is to maintain the output voltage in a load transient event. A second stage filter is added to attenuate the RMS current going into the large value electrolytic capacitors at the final output. This filter is necessary because the DC voltage of a ceramic capacitor must be derated and because the boost topology has a slow loop response due to the presence of a right-half-plane zero in the boost transfer function. In this reference design, C4 through C7 are the first stage output capacitors in the U1 phase, and C28 through C31 are the output capacitors for the second phase. These are all 4.7- μ F, 80-V capacitors. The high voltage rating ensures the total capacitance value does not drop significantly when the output is set to 40 V. The second low-pass filter consists of L3, C20 through C23, C36, and C37.

The switch and synchronous rectifier transistors chosen are automotive rated and have low $R_{DS(on)}$. Due to the high peak current, two transistors are paralleled to reduce heat dissipation in the switch transistors. The synchronous rectifier does not dissipate as much power, so only one transistor is needed; however, this reference design provides enough space for two.

The output voltage can track a 500-Hz sine wave signal with little distortion. Consequently, the LM25122-Q1 has to charge and discharge the output capacitors from 16 V to 40 V then back to 16 V at a rate of 500 Hz. During the discharging event, the synchronous FET is discharging current from the output and returning the current back to the input, which creates a negative voltage across the current sense amplifier. The differential current sense amplifier on the LM25122-Q1 does not support negative current

sense. Therefore, a level shift circuit must be implemented to bias the no-load current sense value to the middle of the dynamic range. The bias circuit consists of D1, R5, and R6 in phase 1 and D3, R26, and R27 in phase 2. This implementation allows the amplifier to transition between the current limit threshold and zero, which ensures regulation during a tracking event. Due to the level shift implementation, a 1-mΩ current sense resistor is used to ensure full load delivery of the charging current during the tracking event.

The operation mode is set for diode emulation mode by tying U1, pin 13 to ground through R17. In FPWM mode, with a pre-biased output at no load, a large reverse current upon start-up is potentially destructive. Selecting diode emulation mode prevents potential large reverse currents. The offset provided to the current sense amplifier forces continuous conduction mode during all conditions of operation, even with the mode pin set to diode emulation mode.

UVLO is set so the regulator starts operating when the input voltage is above 7.5 V. The input voltage is filtered by R10 and C13. R10 provides U1's V_{IN} connection with some isolation from the switching transients on V_{IN} .

2.3.2 Tracking Control

The tracking control circuit is part of the output voltage feedback network for the power supply. The tracking control point is TP3, which is also labeled PWM on the schematic. Resistors R7, R9, and R15 form the normal part of the output voltage feedback network. Resistors R11, R12, and R13 along with capacitors C16 and C17 form an input filter for the PWM signal. R13, C17, R12, and C16 form a low-pass filter that filters a PWM signal. The PWM signal need not be PWM. This signal can also be a sine wave of 500 Hz or less, or a DC voltage can be applied to control the boost output voltage.

The boost regulator drives the output voltage to maintain 1.2 V at the feedback pin on U1. Changing the voltage at TP3 can therefore control the output voltage. V_{OUT} is inversely proportional to the voltage at TP3. The PWM input design works with a 3.3-V PWM output from a microprocessor. The resistor values of the PWM input network are chosen so the boost regulator provides a 40-V output when a 3.3-V PWM signal with a 10% duty cycle is present. If the PWM signal has a 90% duty cycle, the boost output is 16 V.

The PWM signal must be at least 100 kHz. Otherwise, the filter network cannot filter the noise from the PWM signal well and the noise will appear in the output of the boost converter. If the values of C16 and C17 are increased, more filtering would be provided to the control signal. However, it would take longer for the boost output voltage to respond to changes in the control signal, which lowers the frequency that the power supply output responds to. In an actual system, the control signal varies based on the level, or volume, setting of an audio signal.

3 Hardware Setup, Testing Requirements, and Test Results

3.1 Hardware Setup

In addition to the setup defined in [图 5](#), three 6.8-mF, 65-V rated electrolytic capacitors are used to damp the wiring inductance of the input supply for all test data taken on this design guide.

3.2 Testing and Results

3.2.1 Test Setup

[图 5](#) shows the setup for the efficiency test.

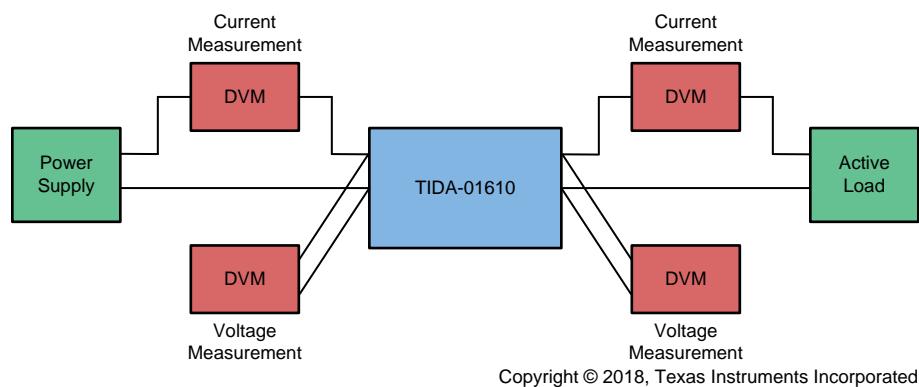


图 5. Efficiency Test Setup Diagram

3.2.2 Test Results

3.2.2.1 Efficiency

The power output efficiency is plotted in [图 6](#), [图 7](#), [图 8](#), and [图 9](#). In all cases, the efficiency is above 90% for loads above 0.5 A and above 95% for loads above 2 A.

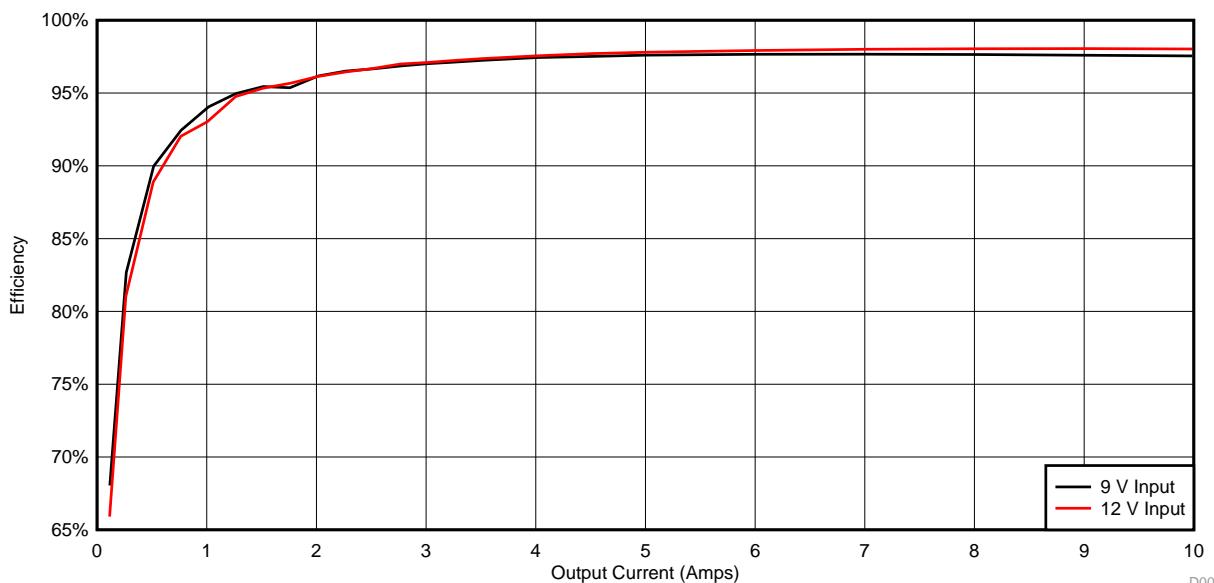


图 6. 16-V Output Efficiency

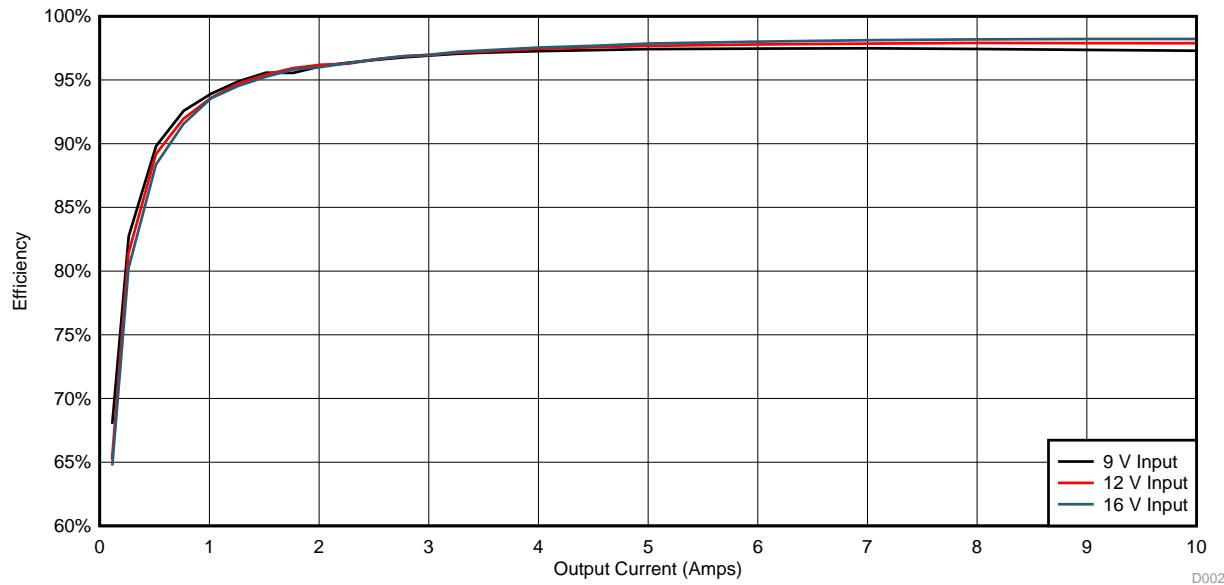


图 7. 20-V Output Efficiency

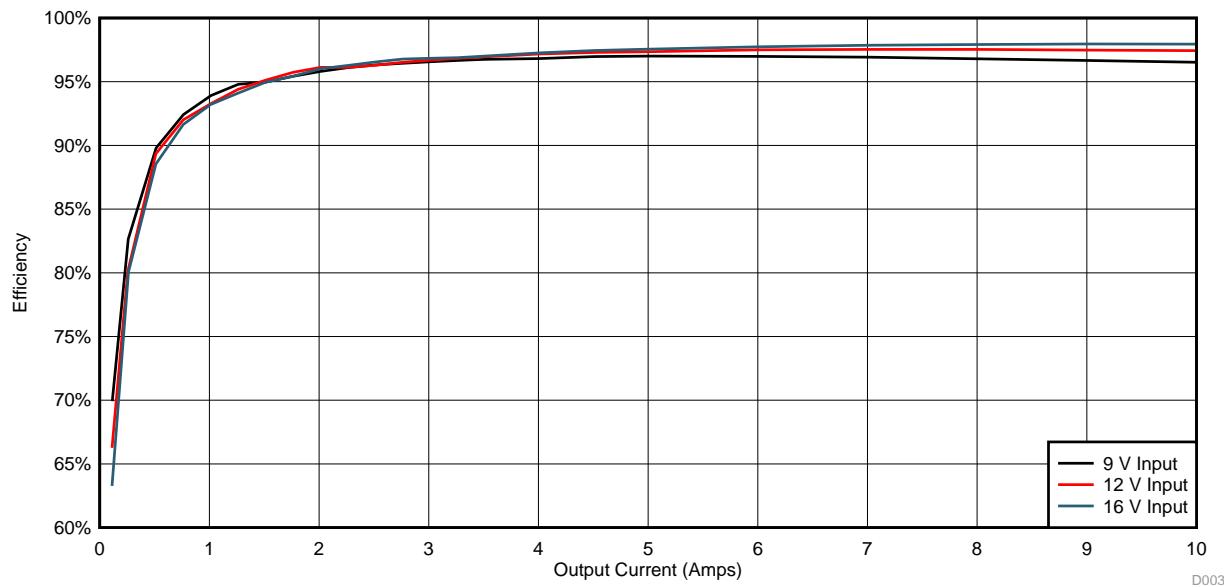


图 8. 30-V Output Efficiency

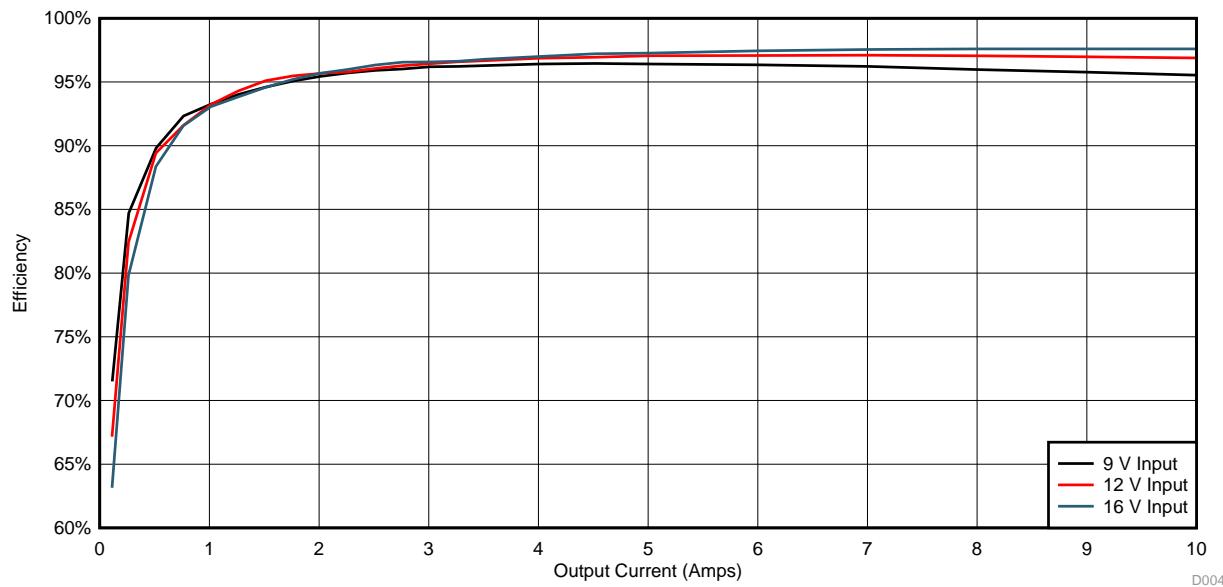


图 9. 40-V Output Efficiency

3.2.2.2 Switching Waveforms and Output Ripple

The switching waveforms and output ripple are measured with oscilloscope probes connected to TP1 (SW1), TP2 (SW2), and the V_{OUT} test points shown in 图 4. In the oscilloscope traces in 图 10, the yellow trace is the switch node for the master LM25122-Q1, the blue trace is the slave switch node, and the pink trace is the output ripple and noise. The worst cast output ripple is about 180 mVp-p with a 9-V input and a 40-V output, as shown in 图 18.

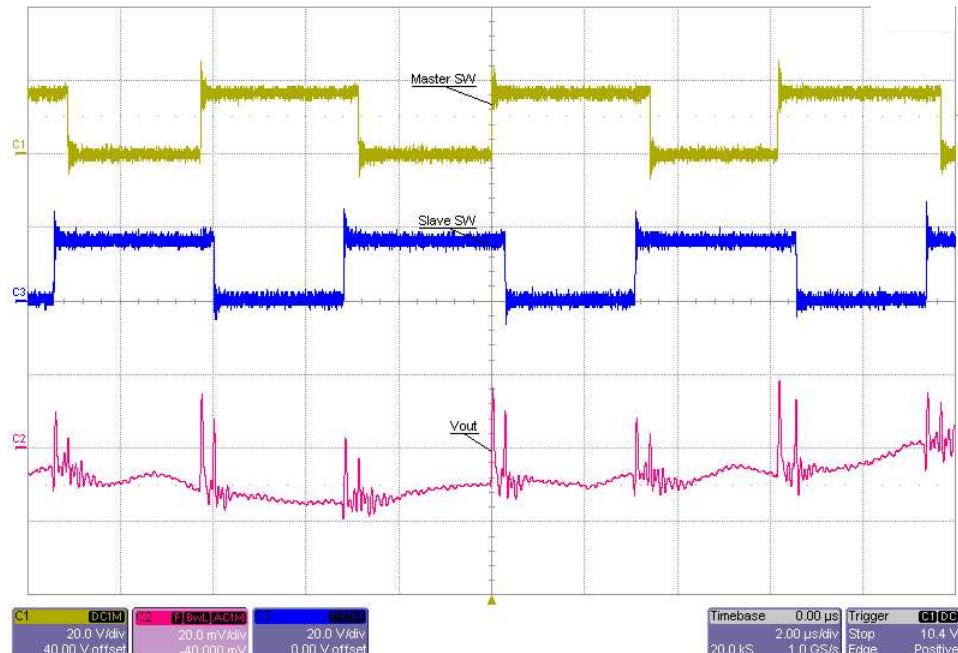


图 10. 9-V Input, 16-V Output, Full Load

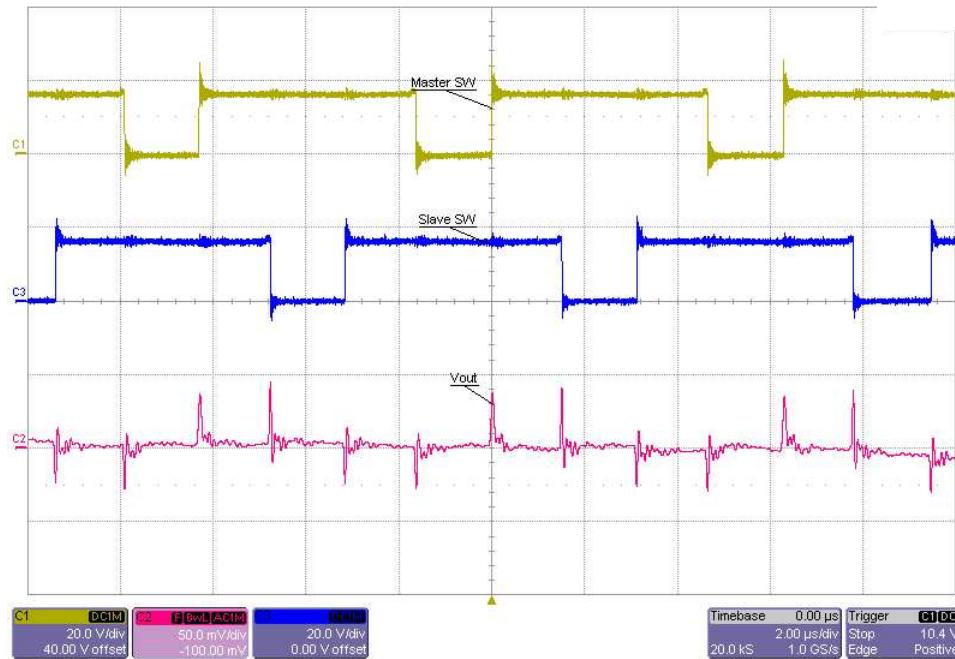


图 11. 12-V Input, 16-V Output, Full Load

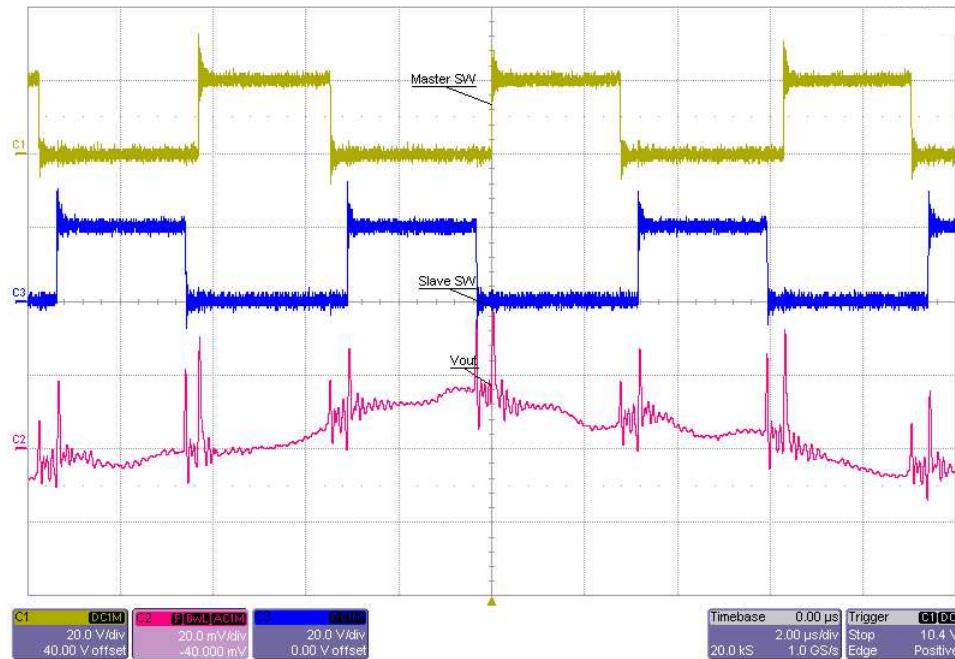


图 12. 9-V Input, 20-V Output, Full Load

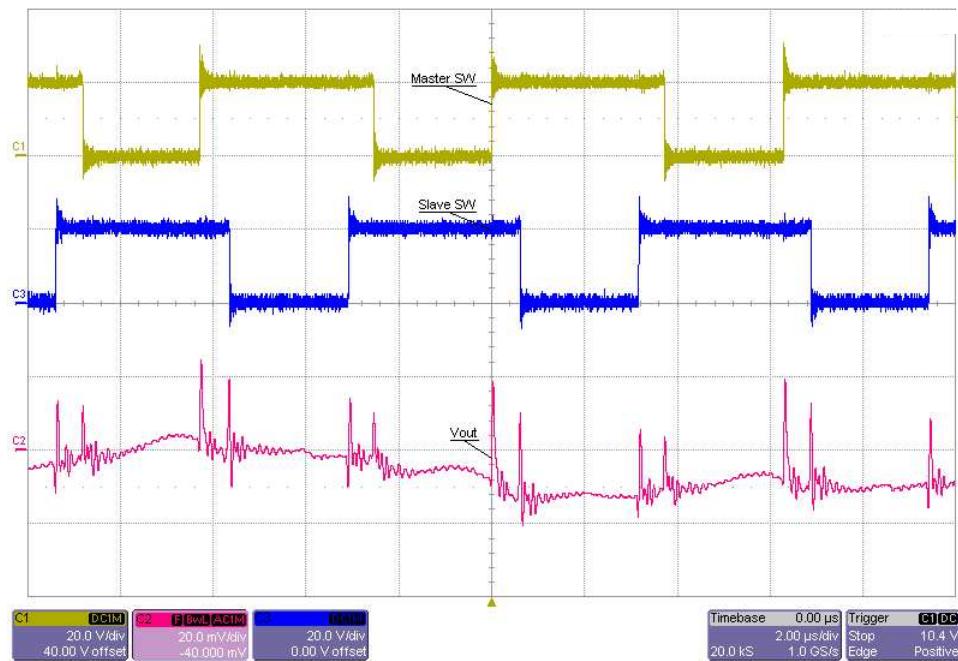


图 13. 12-V Input, 20-V Output, Full Load

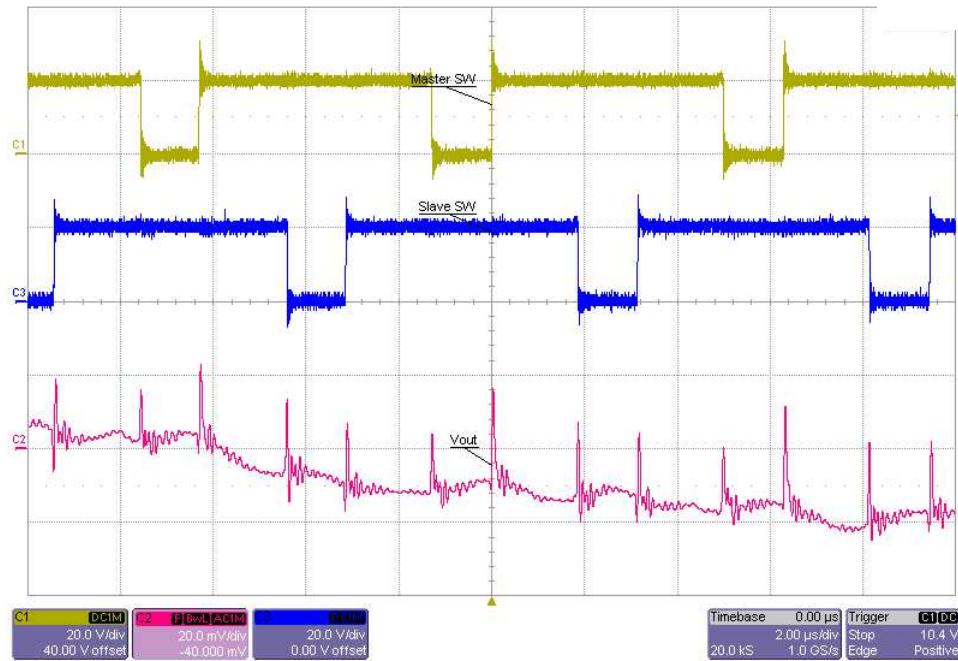


图 14. 16-V Input, 20-V Output, Full Load

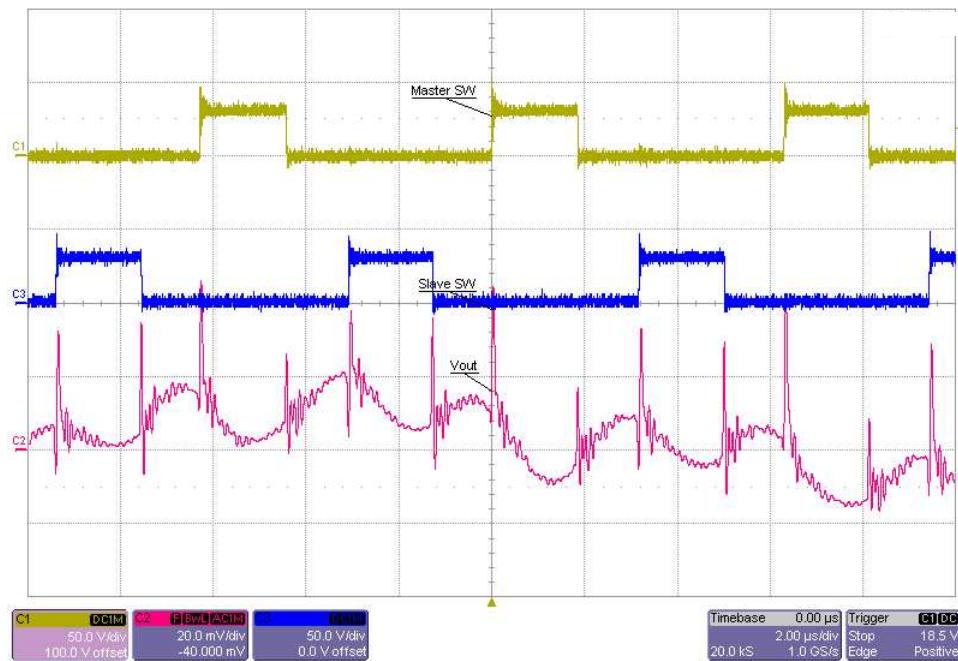


图 15. 9-V Input, 30-V Output, Full Load

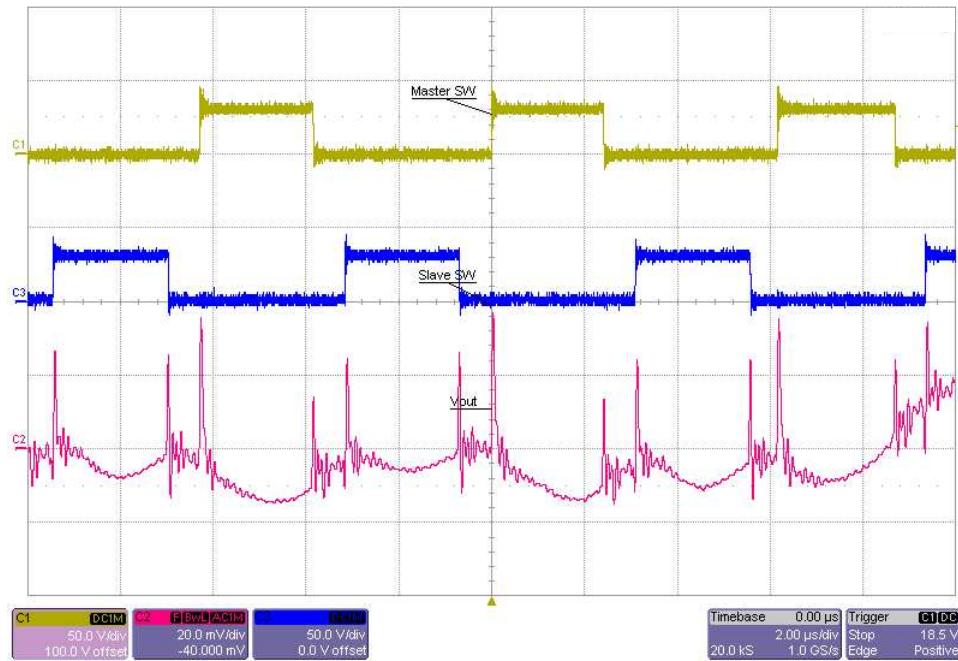


图 16. 12-V Input, 30-V Output, Full Load

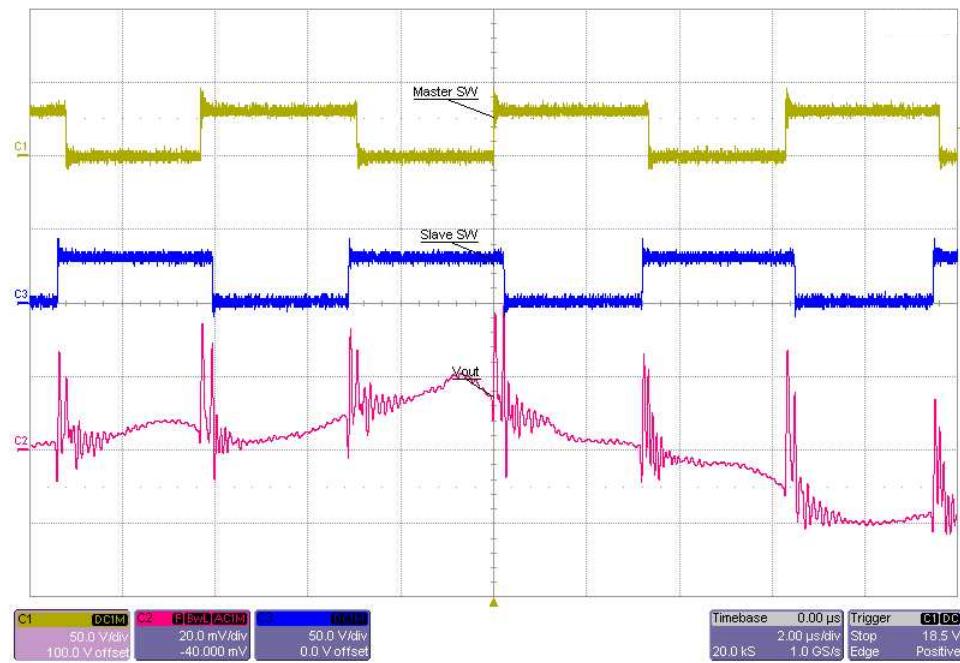


图 17. 16-V Input, 30-V Output, Full Load

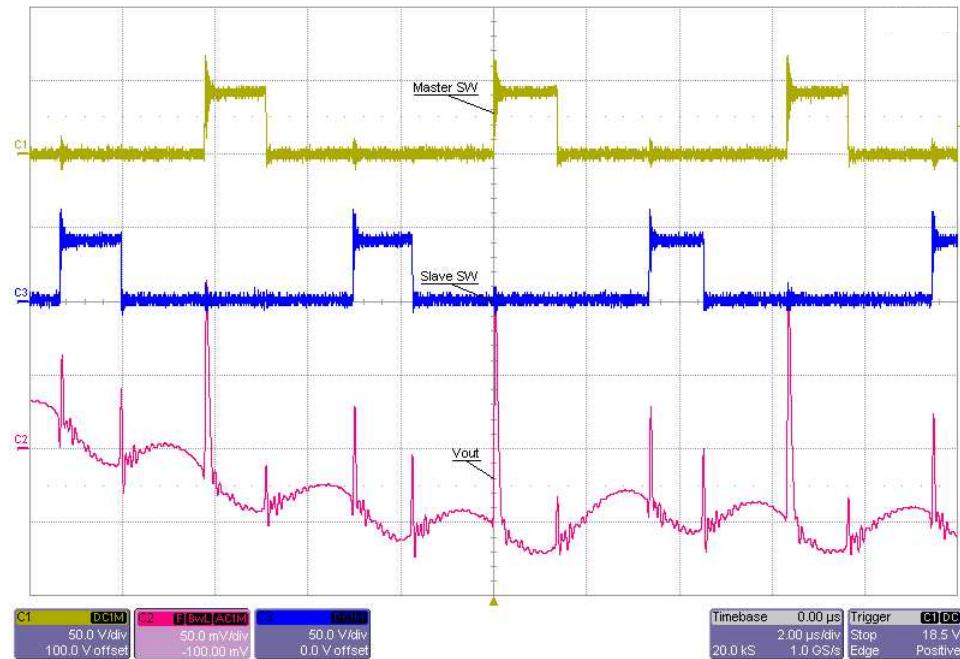
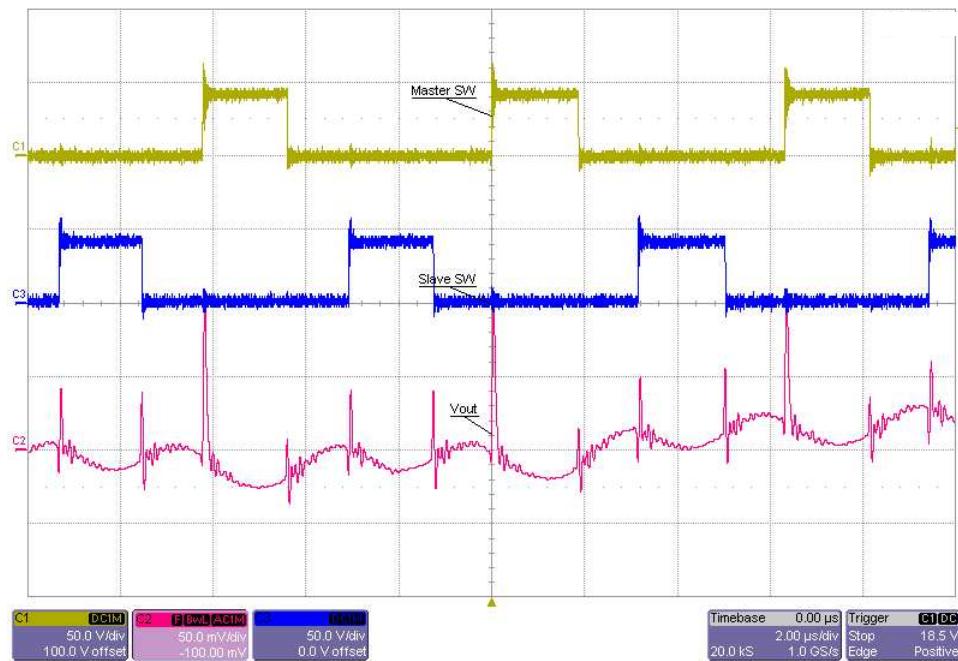
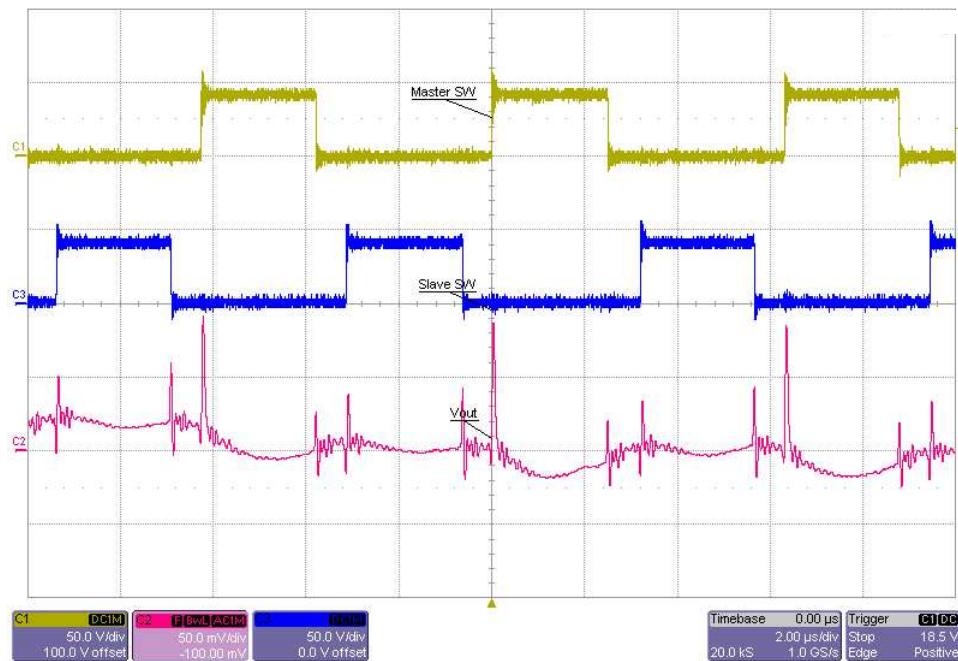


图 18. 9-V Input, 40-V Output, Full Load


图 19. 12-V Input, 40-V Output, Full Load

图 20. 16-V Input, 40-V Output, Full Load

3.2.2.3 Start-Up Transient

The start-up transient behavior is measured with oscilloscope probes connected to the input and output voltages and an inductive current probe to measure the output current to the load. In the oscilloscope traces in this section, the yellow trace is the input voltage, the blue trace is the output voltage, and the green trace is the output current. At start-up, the output reaches 40 V in about 22 ms for input voltages of 12 V and 16 V and 23 ms for an input voltage of 9 V.

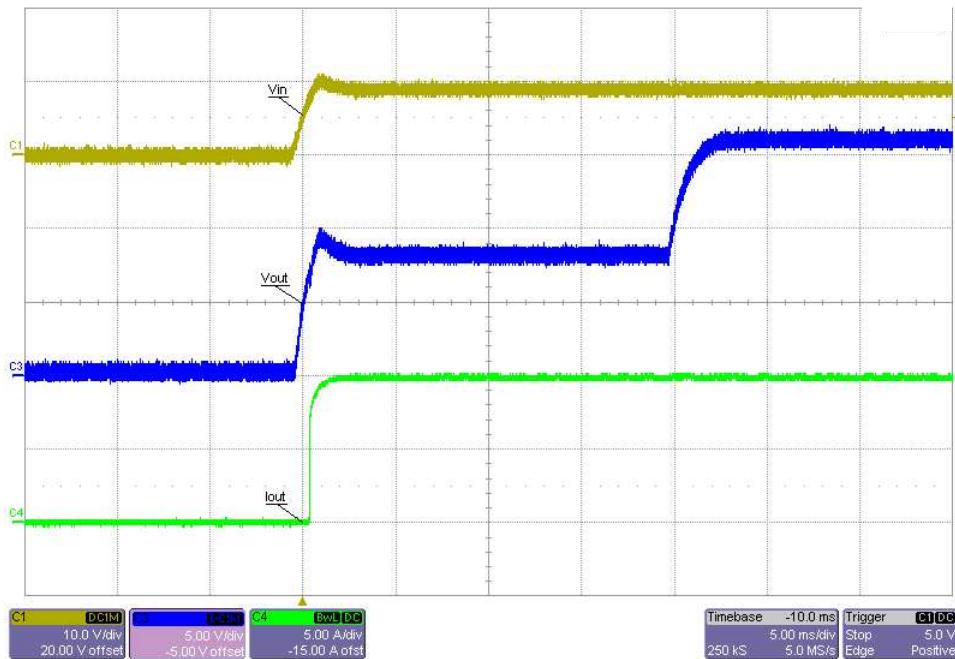


图 21. 9-V Input, 16-V Output, 10-A Load Start-up

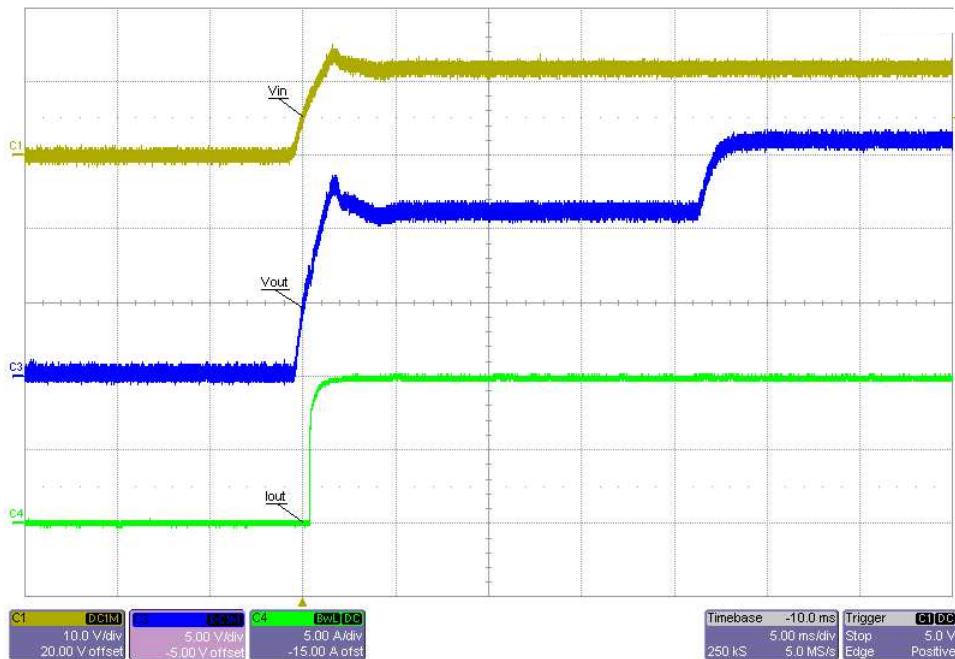


图 22. 12-V Input, 16-V Output, 10-A Load Start-up

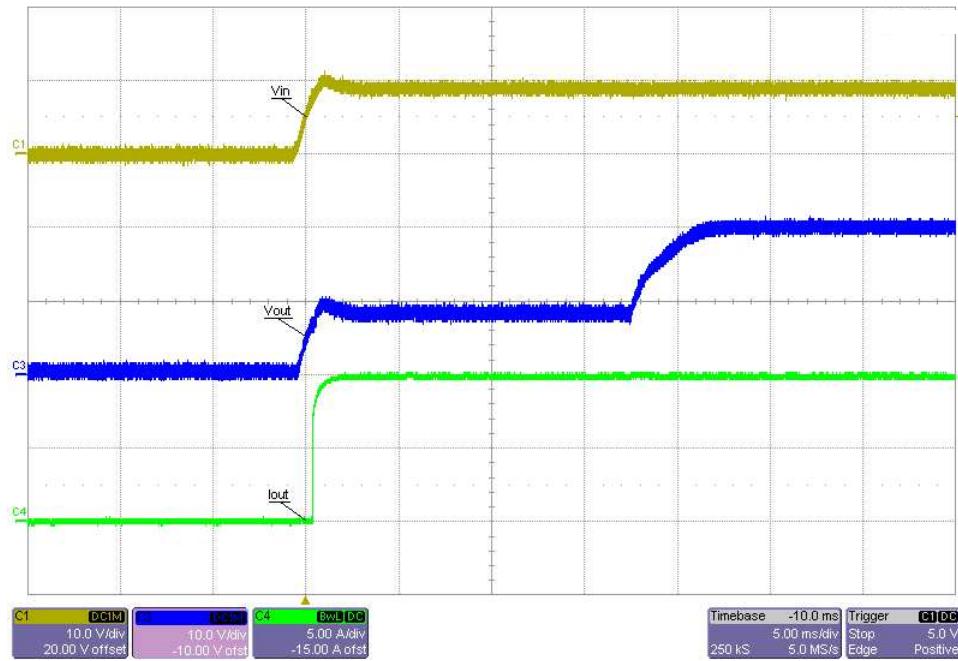


图 23. 9-V Input, 20-V Output, 10-A Load Start-up

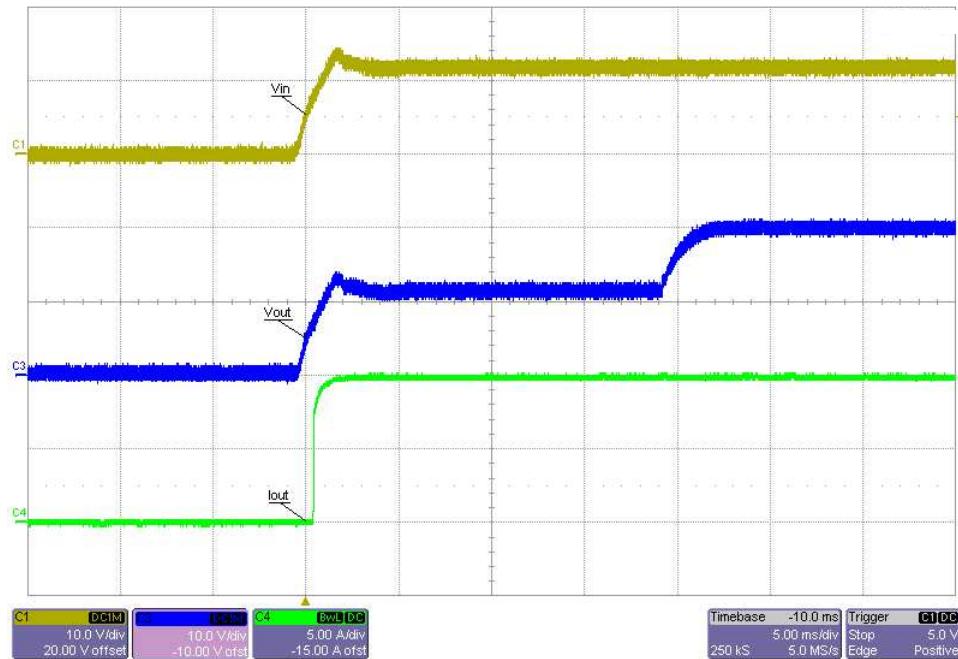


图 24. 12-V Input, 20-V Output, 10-A Load Start-up

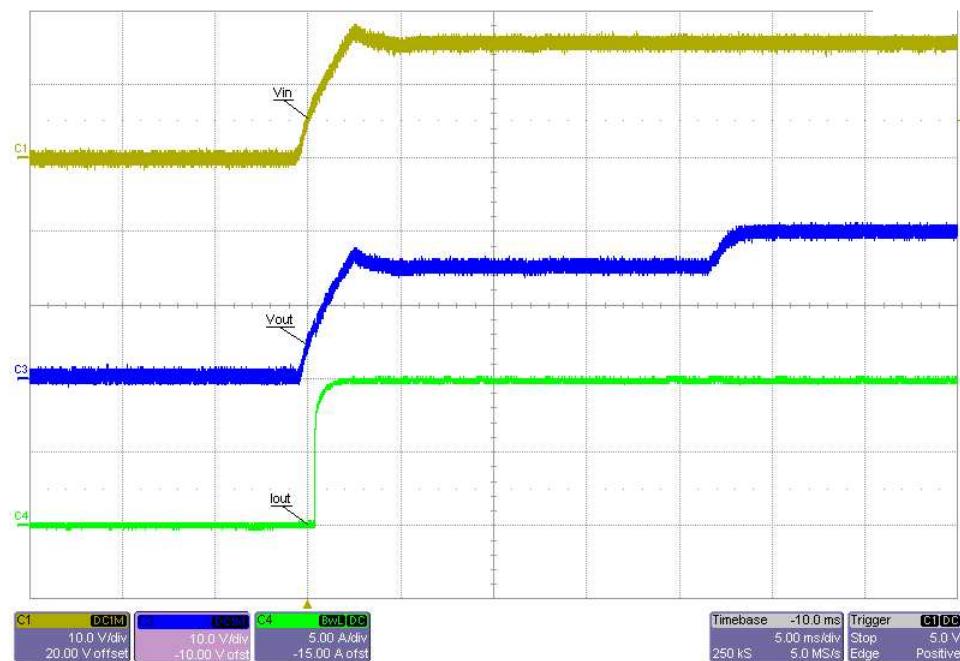


图 25. 16-V Input, 20-V Output, 10-A Load Start-up

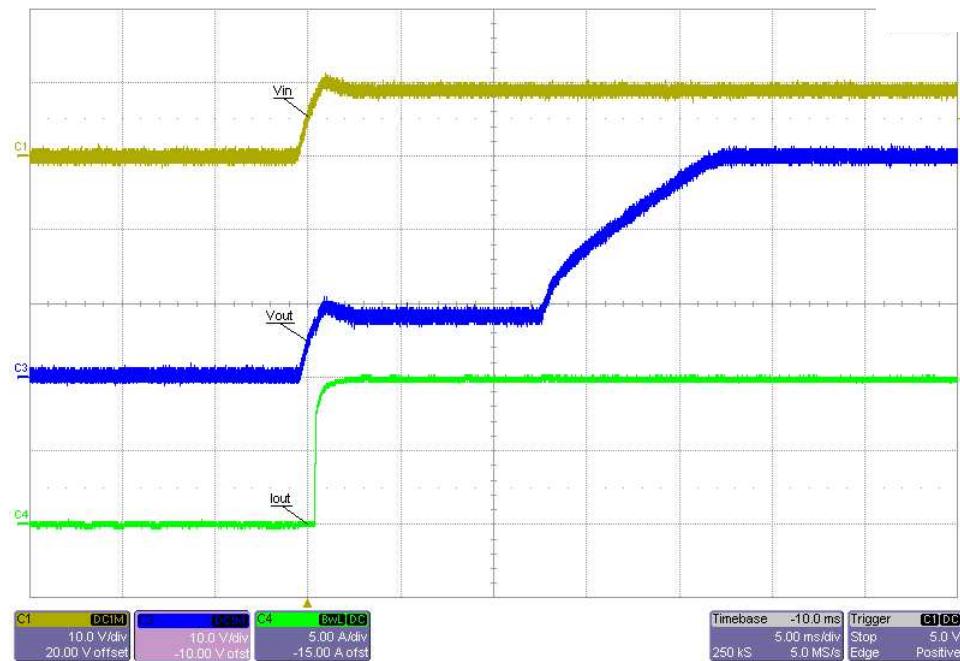


图 26. 9-V Input, 30-V Output, 10-A Load Start-up

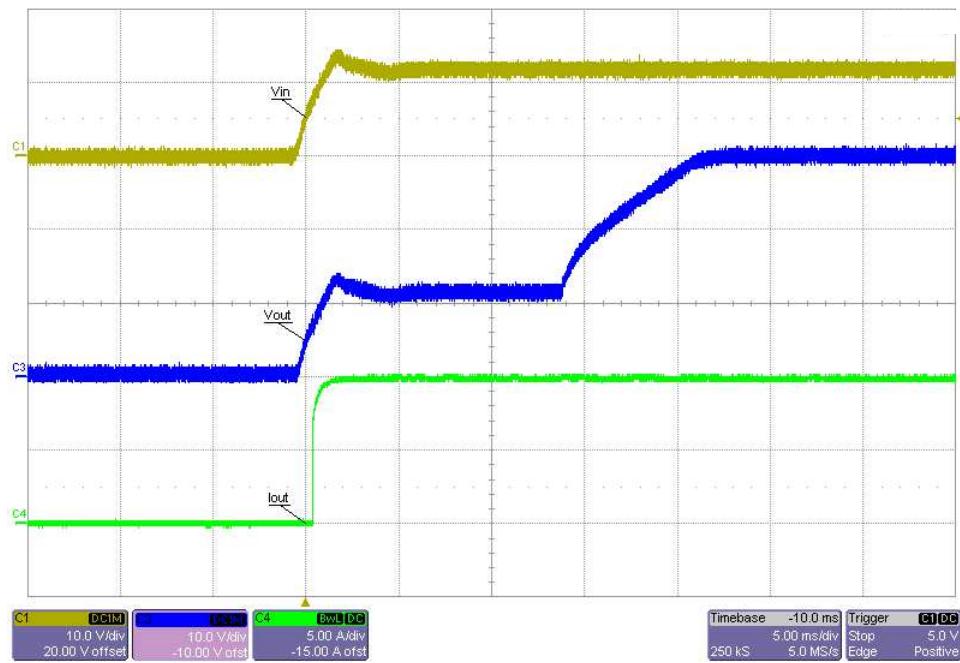


图 27. 12-V Input, 30-V Output, 10-A Load Start-up

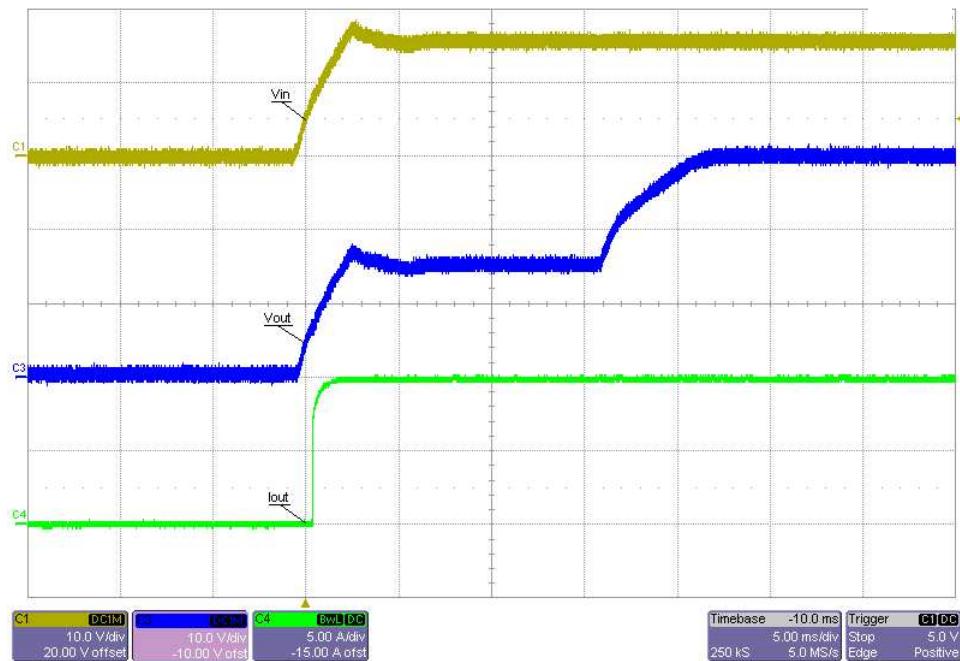


图 28. 16-V Input, 30-V Output, 10-A Load Start-up

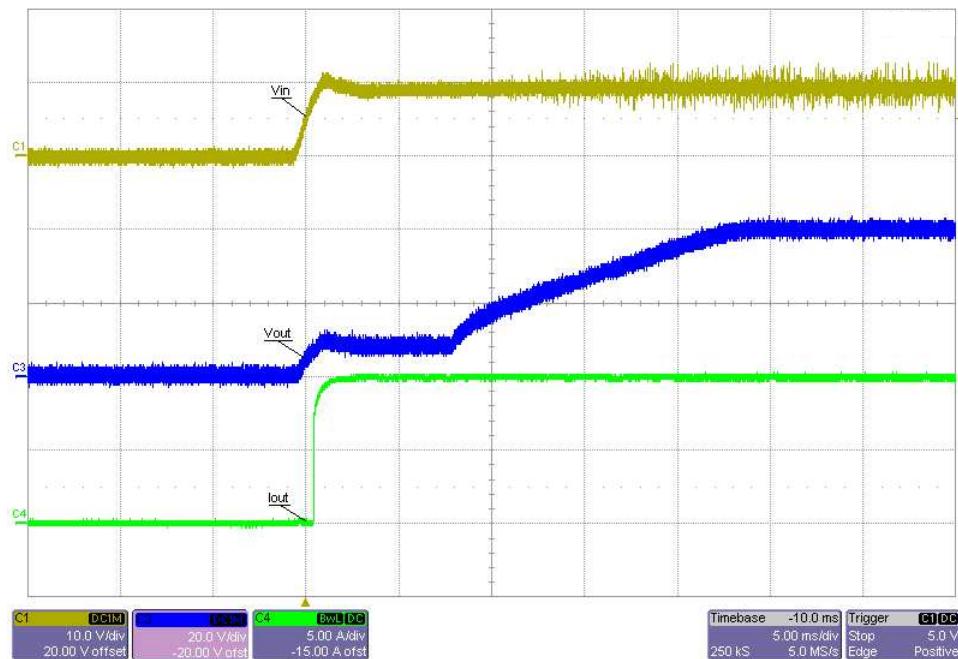


图 29. 9-V Input, 40-V Output, 10-A Load Start-up

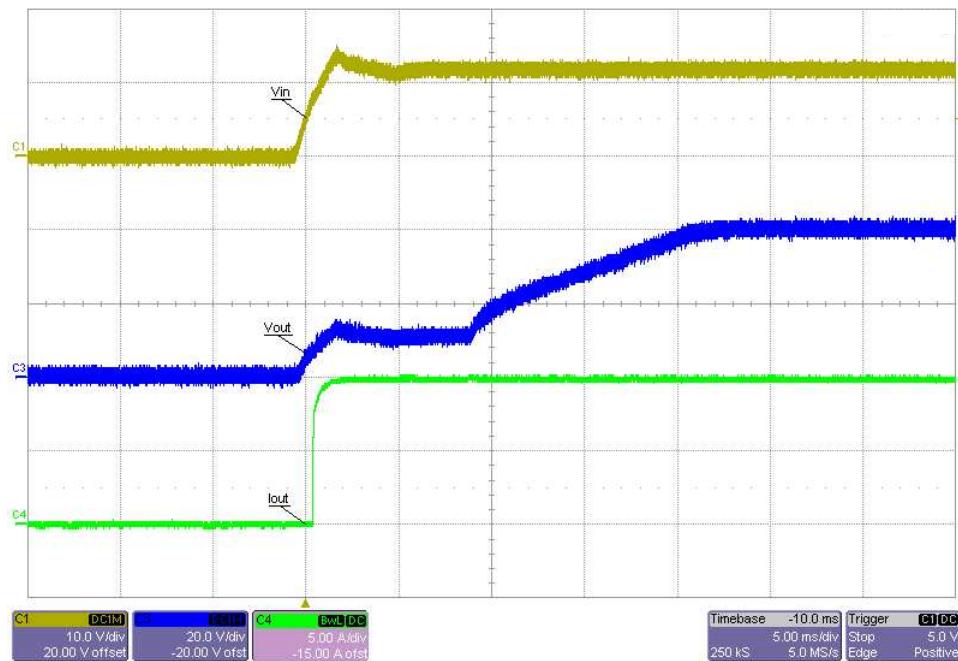


图 30. 12-V Input, 40-V Output, 10-A Load Start-up

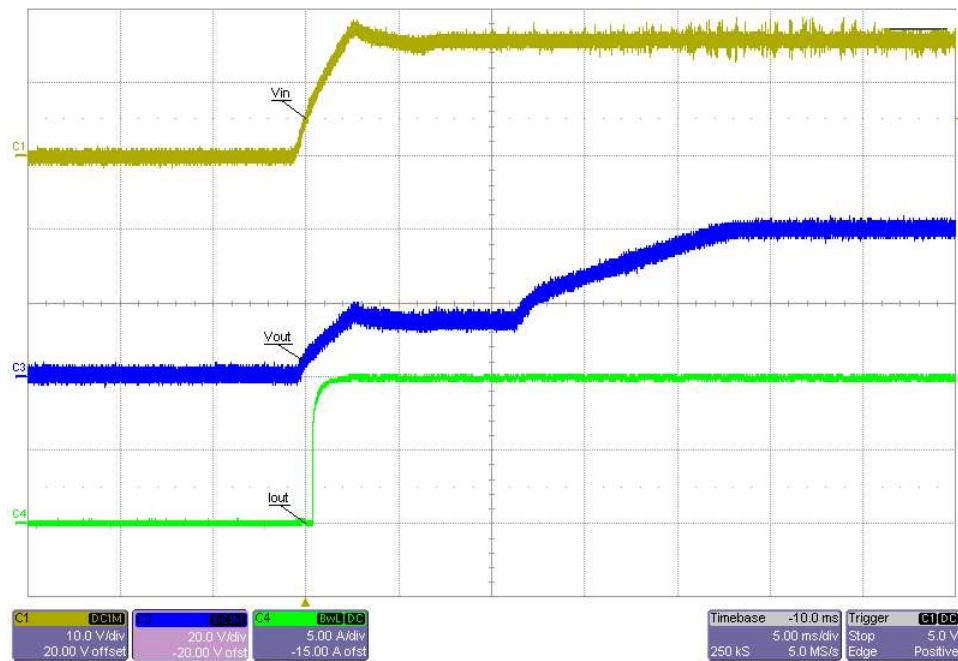


图 31. 16-V Input, 40-V Output, 10-A Load Start-up

3.2.2.4 Transient Response

The load step transient response is measured with an oscilloscope probe on the output voltage and an inductive current probe measuring the output current. In the following plots, the pink trace is the output voltage and the green trace is the output current. The load step response is measured with a load step of 5 A to 10 A with input voltages of 9 V, 12 V, and 16 V. Output voltage is set for 40 V because this is the worst case condition. The worst case droop and overshoot occurs when the input voltage is 49 V, as shown in 图 32. The maximum voltage droop is 1.4 V, and the maximum overshoot is 1.2 V.

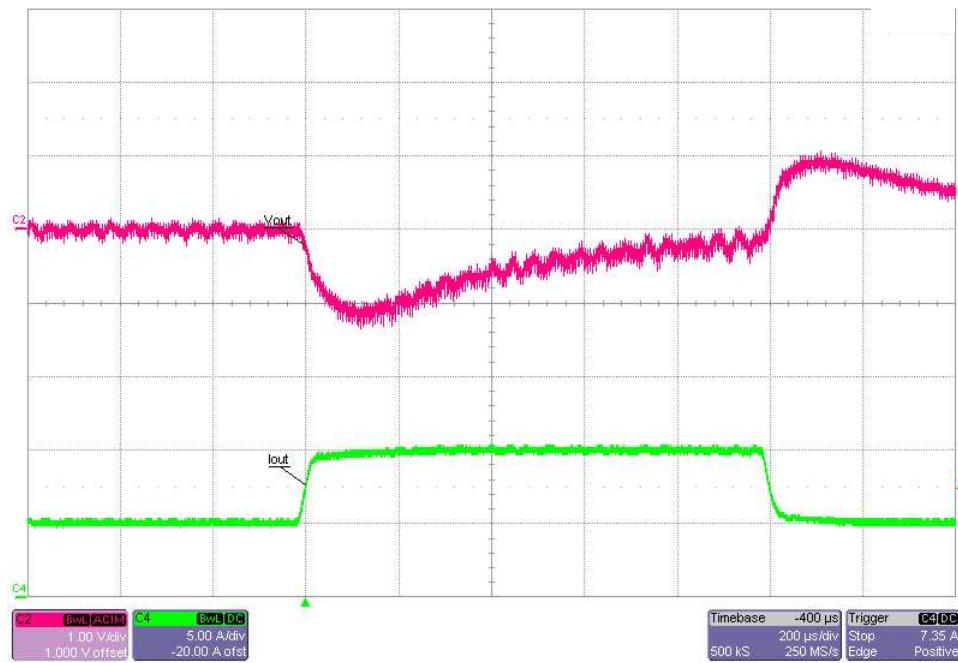


图 32. 9-V Input, 40-V Output, 5-A to 10-A Load Transient

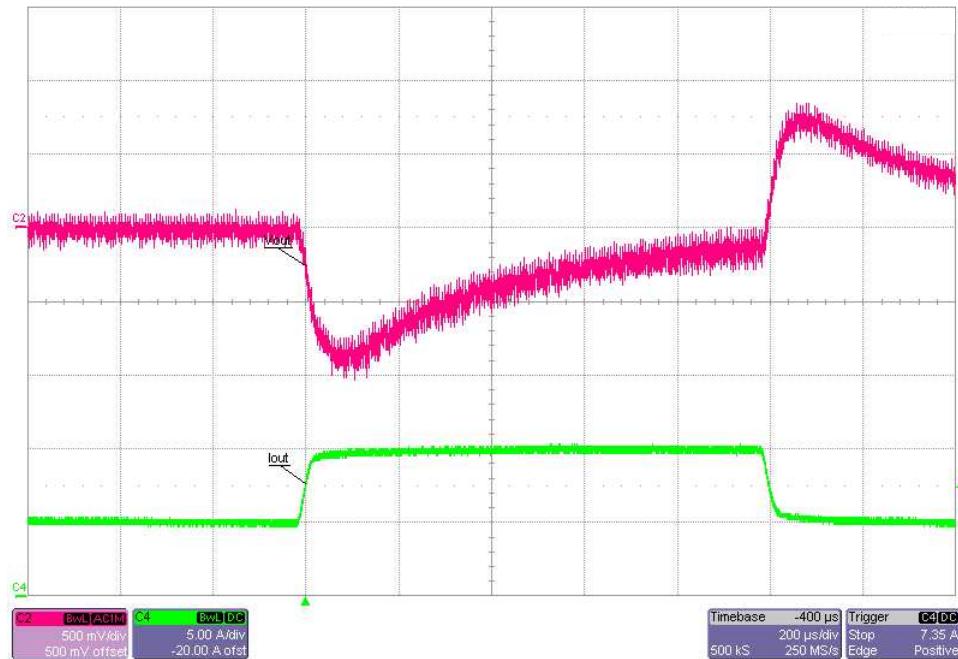


图 33. 12-V Input, 40-V Output, 5-A to 10-A Load Transient

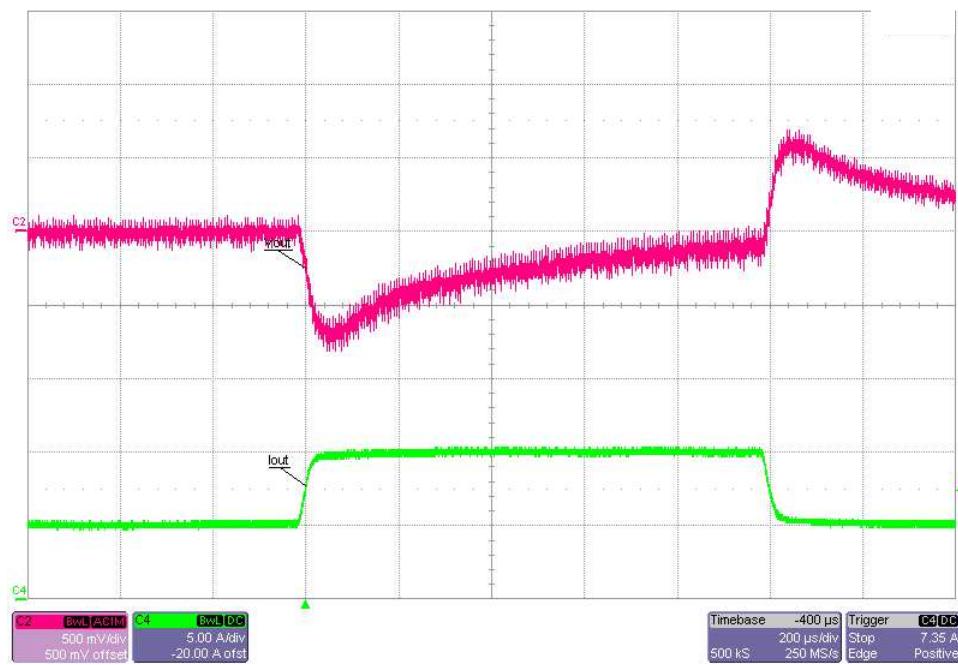


图 34. 16-V Input, 40-V Output, 5-A to 10-A Load Transient

3.2.2.5 Envelope Tracking

图 35 显示了输出电压对 500-Hz 跟踪信号的响应。跟踪信号从 0.3 V 变化到 3 V。在以下图表中，黄色轨迹是跟踪信号，粉色轨迹是输出电压，蓝色轨迹测量补偿电压，绿色轨迹测量输入电流。输入电压在两种情况下均为 12 V。请注意，输出电压比跟踪电压滞后 285 μ s。

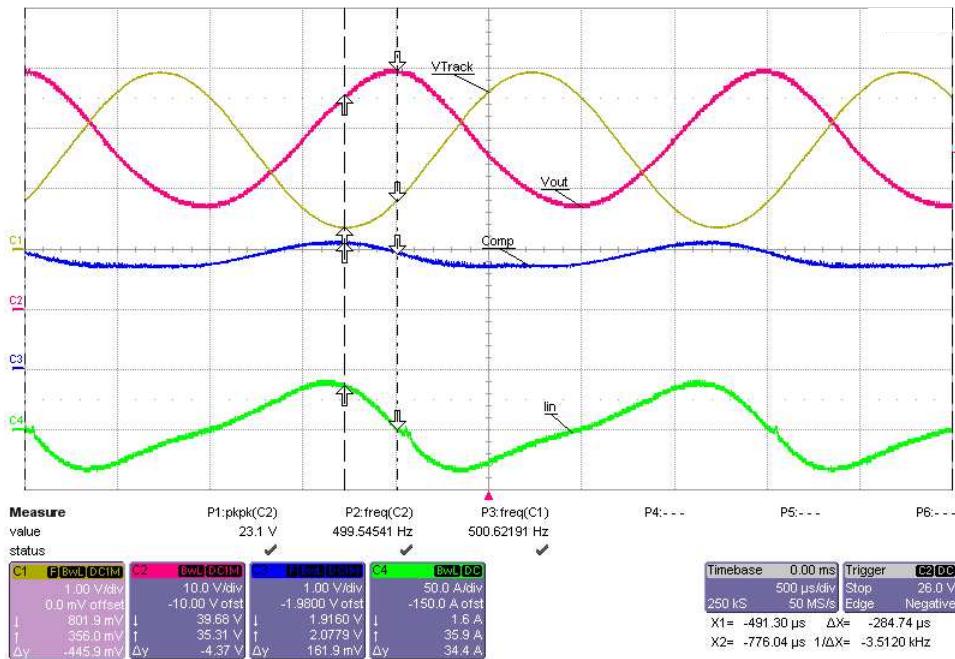


图 35. Tracking Response, 12-V Input, No Load, 500-Hz Tracking Signal

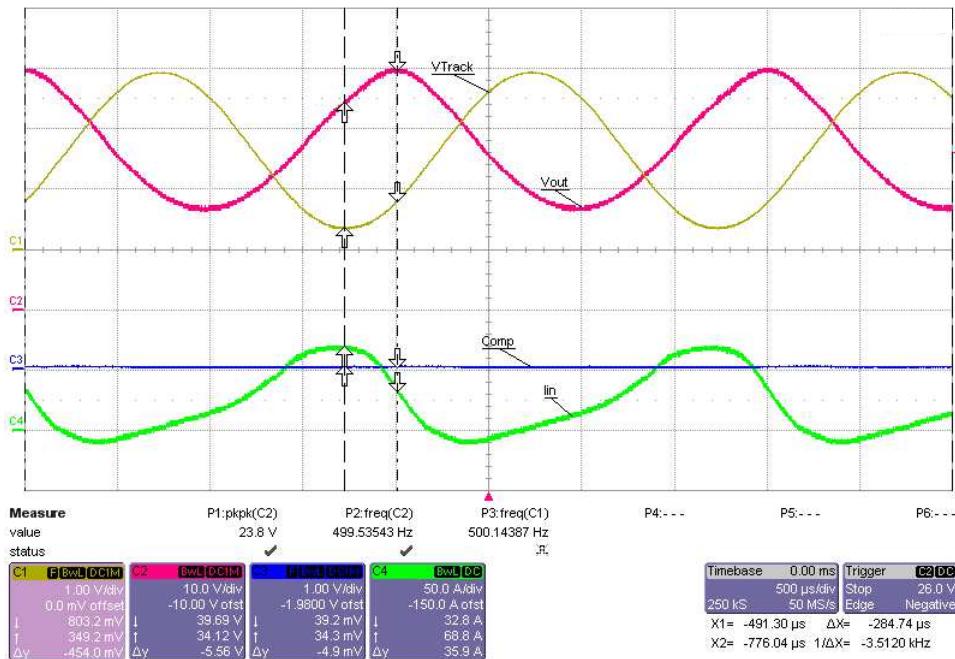


图 36. Tracking Response, 12-V Input, 10-A Load, 500-Hz Tracking Signal

3.2.2.6 Frequency Response

This section shows the gain and phase margin for a 10-A output with the input voltage set to 9 V, 12 V, or 16 V and the output voltage set to 16 V, 24 V, 30 V, or 40 V.

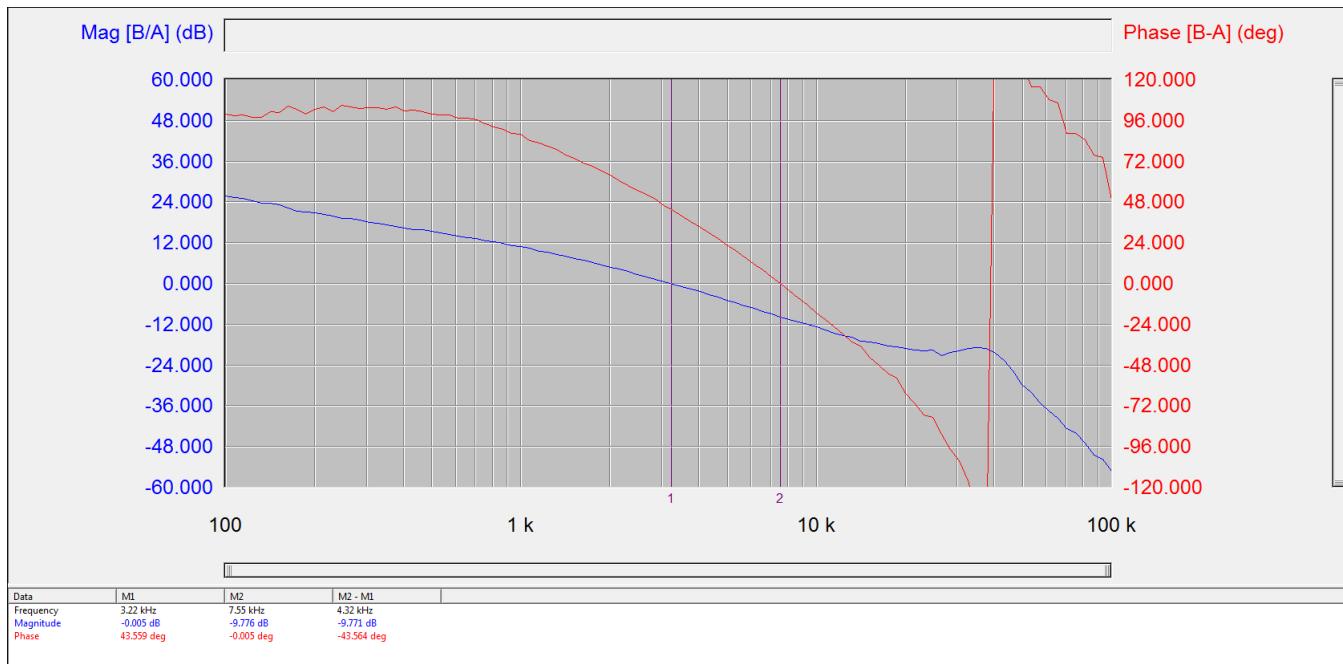


图 37. 9-V Input, 16-V Output, 10-A load: 43.56-Degree Phase Margin, -9.78-dB Gain Margin

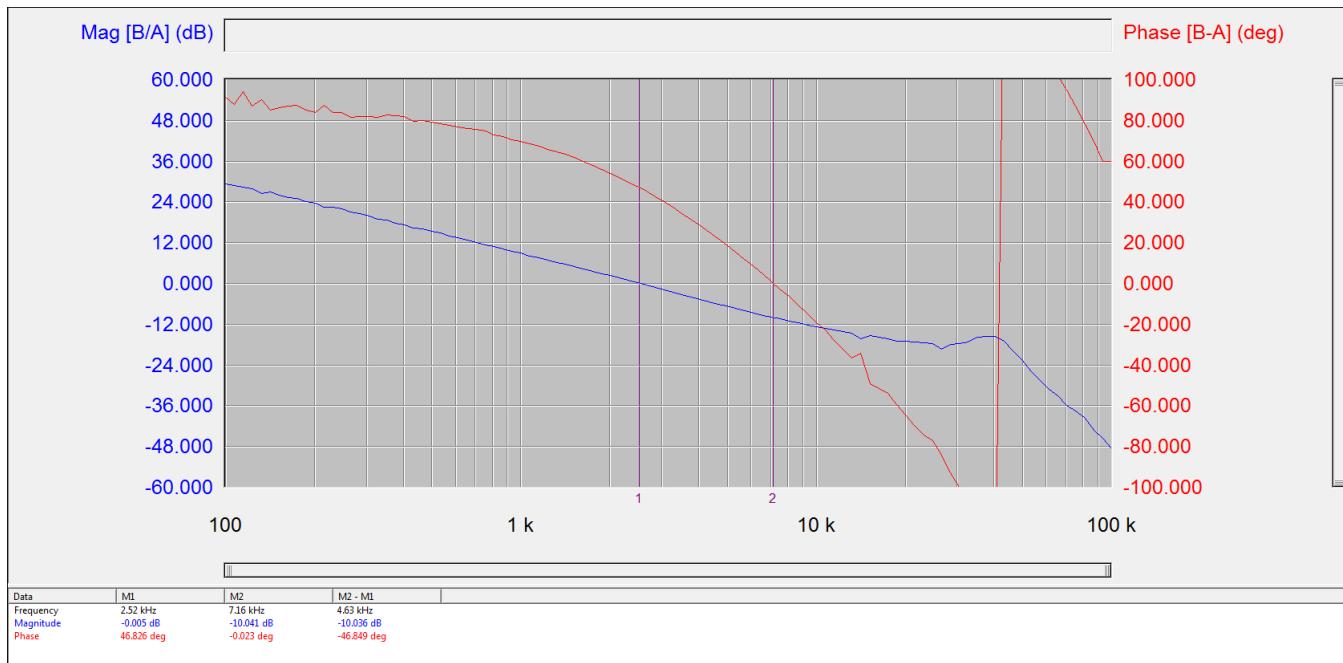


图 38. 9-V Input, 24-V Output, 10-A Load: 46.83-Degree Phase Margin, -10.04-dB Gain Margin

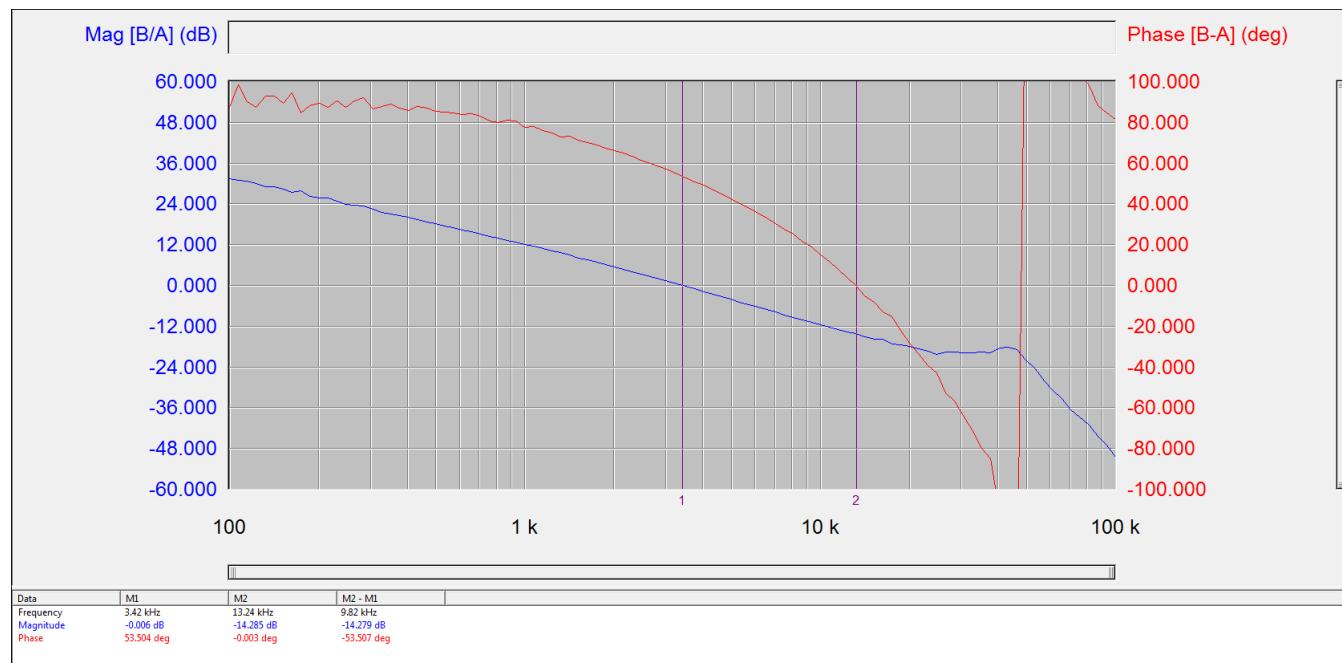


图 39. 9-V Input, 30-V Output, 10-A Load: 48.94-Degree Phase Margin, -10.36-dB Gain Margin

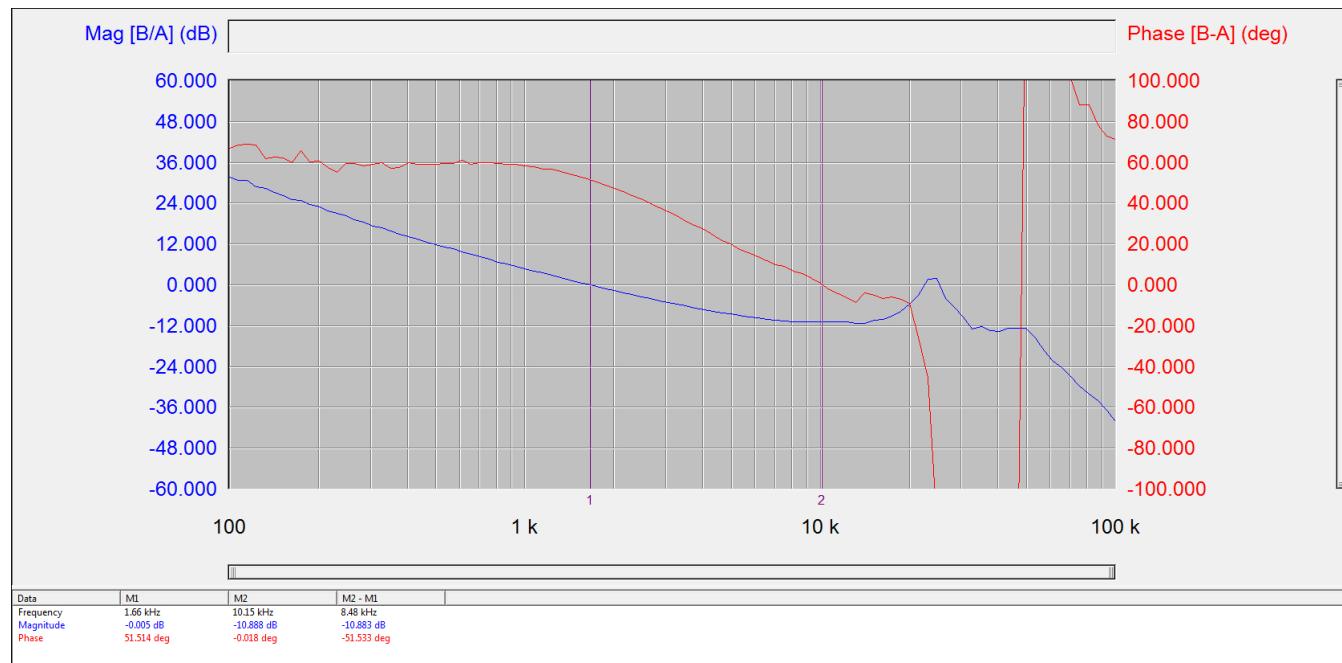


图 40. 9-V Input, 40-V Output, 10-A Load: 51.51-Degree Phase Margin, -10.89-dB Gain Margin

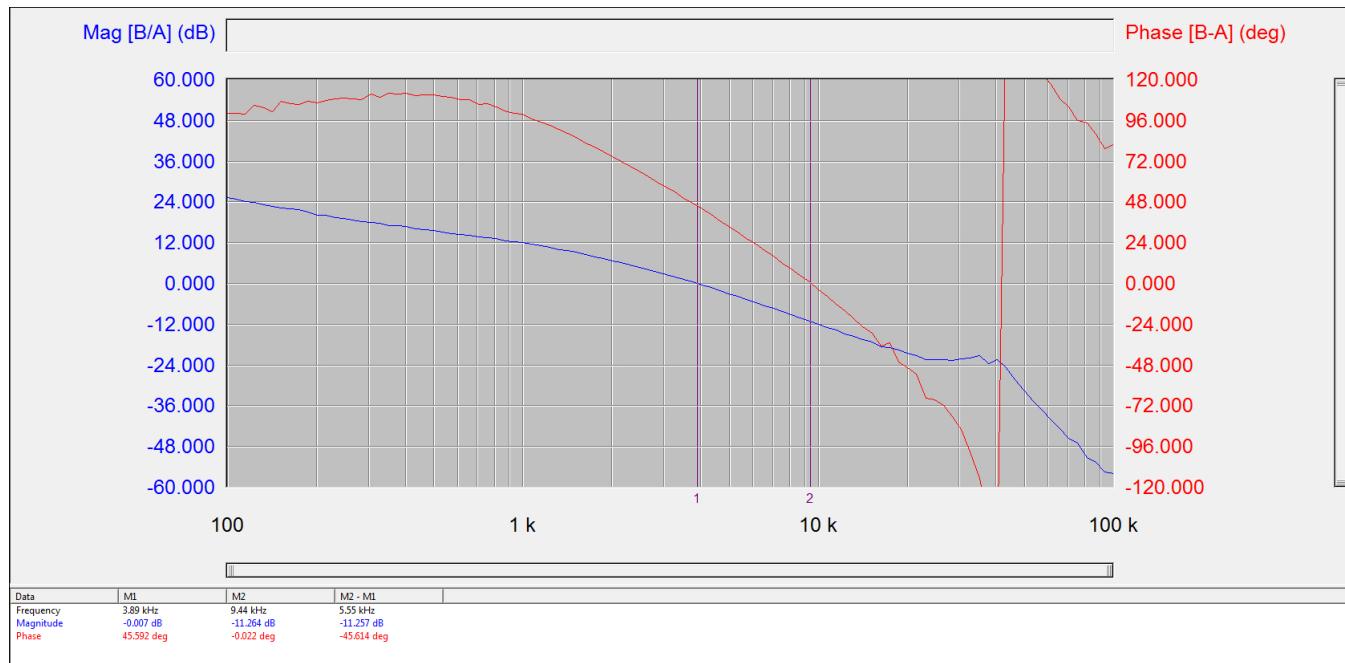


图 41. 12-V Input, 16-V Output, 10-A load: 45.6-Degree Phase Margin, -11.26-dB Gain Margin

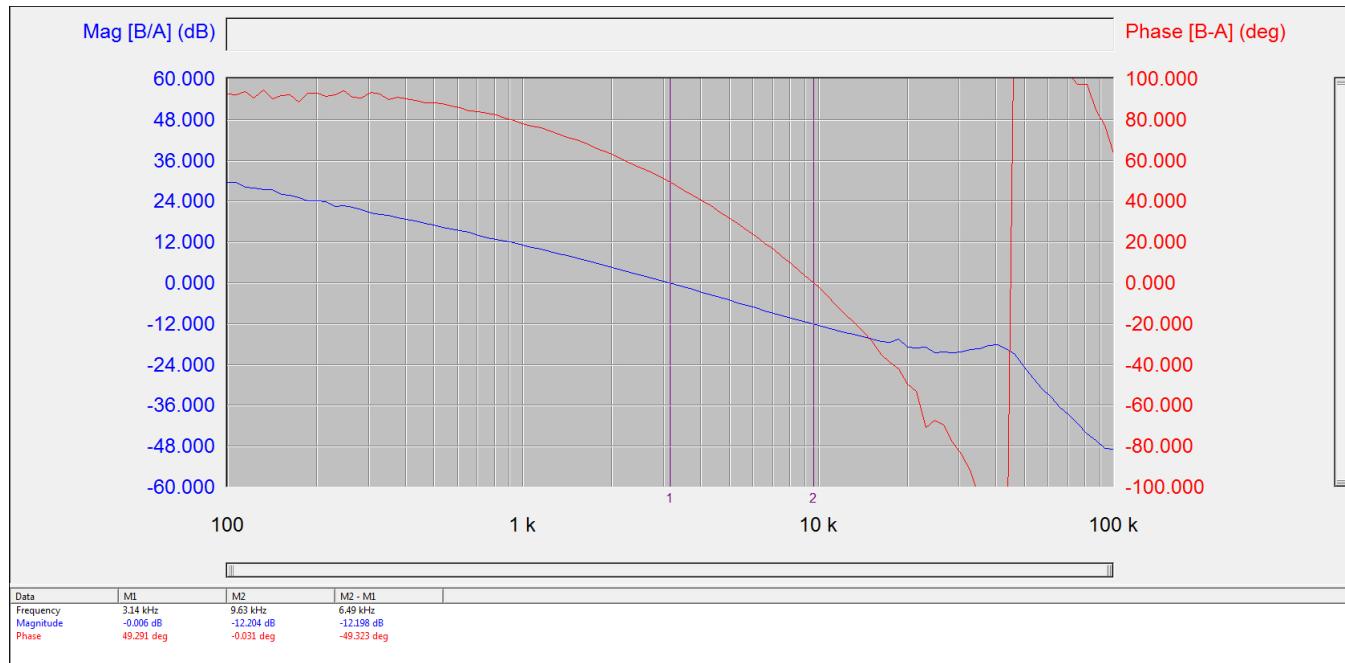


图 42. 12-V Input, 24-V Output, 10-A Load: 49.29-Degree Phase Margin, -12.204-dB Gain Margin

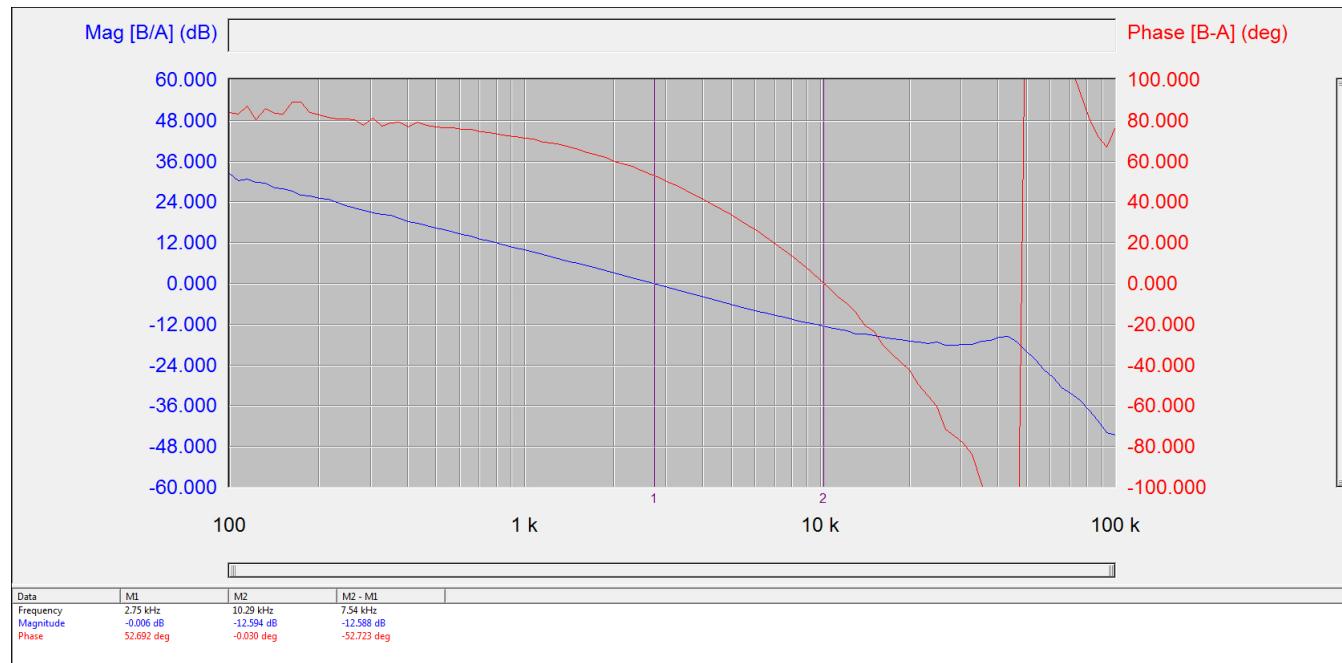


图 43. 12-V Input, 30-V Output, 10-A Load: 52.69-Degree Phase Margin, -12.59-dB Gain Margin

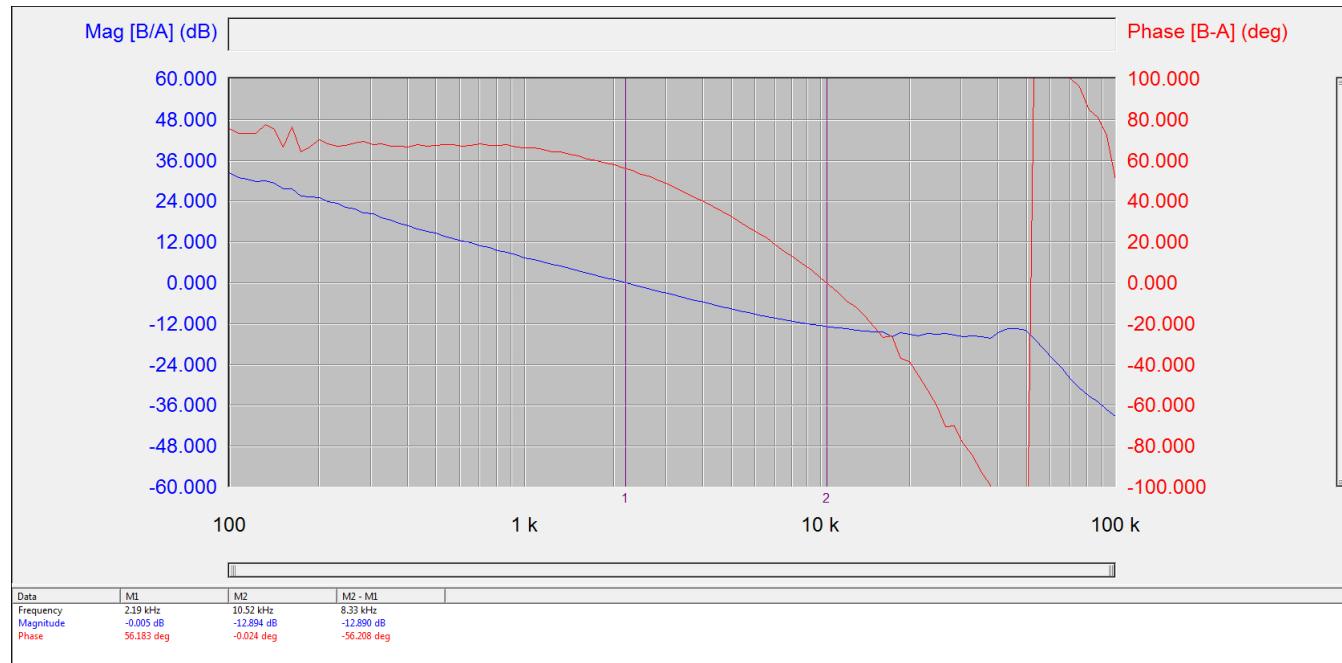


图 44. 12-V Input, 40-V Output, 10-A Load: 56.18-Degree Phase Margin, -12.89-dB Gain Margin

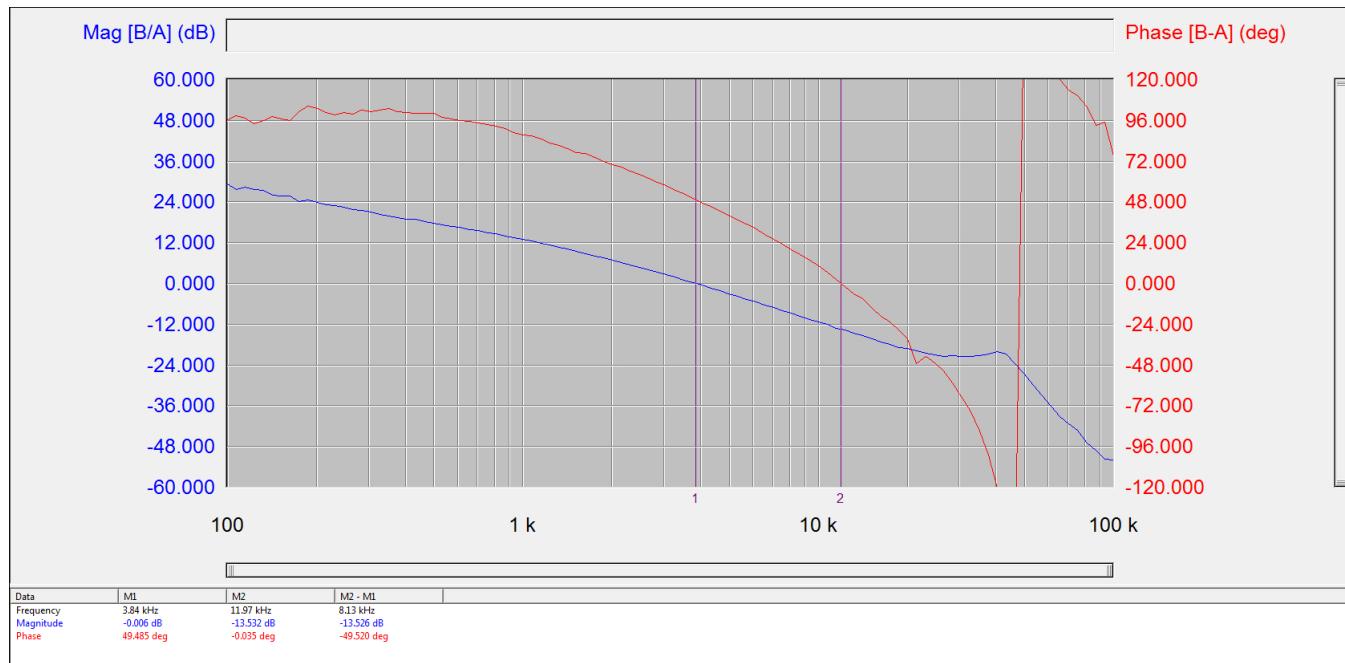


图 45. 16-V Input, 24-V Output, 10-A Load: 49.49-Degree Phase Margin, -13.53-dB Gain Margin

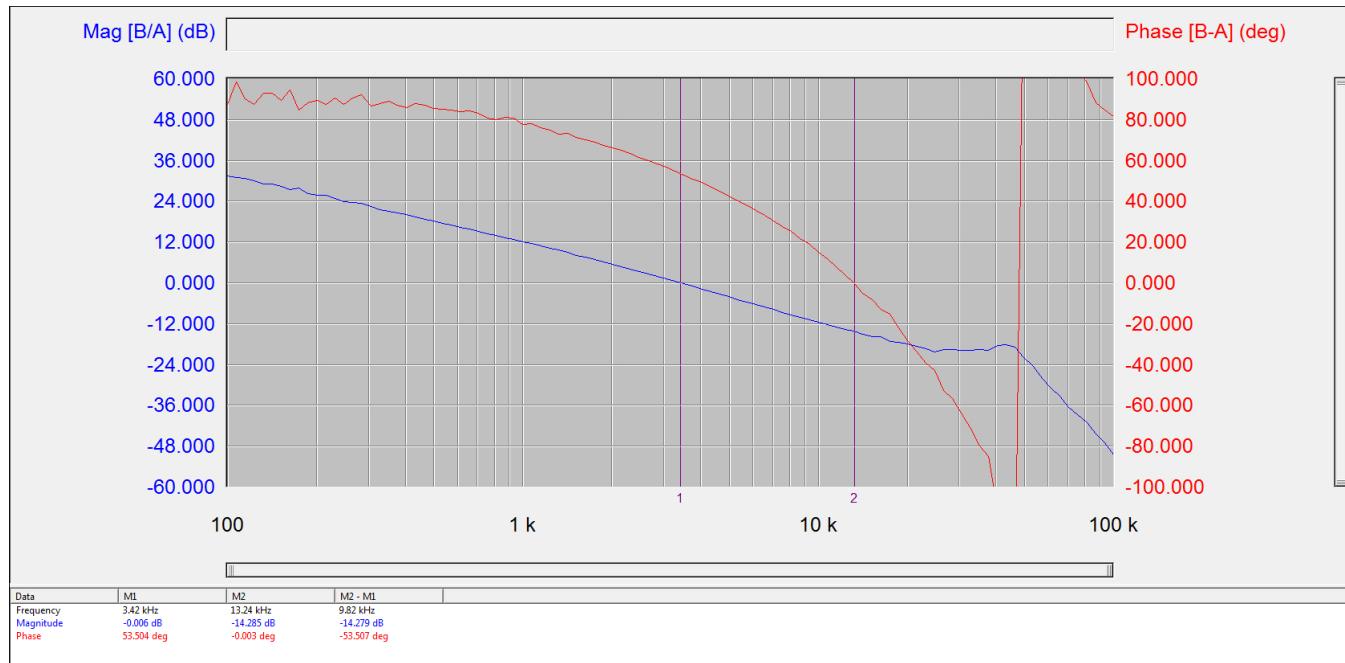


图 46. 16-V Input, 30-V Output, 10-A Load: 53.51-Degree Phase Margin, -14.29-dB Gain Margin

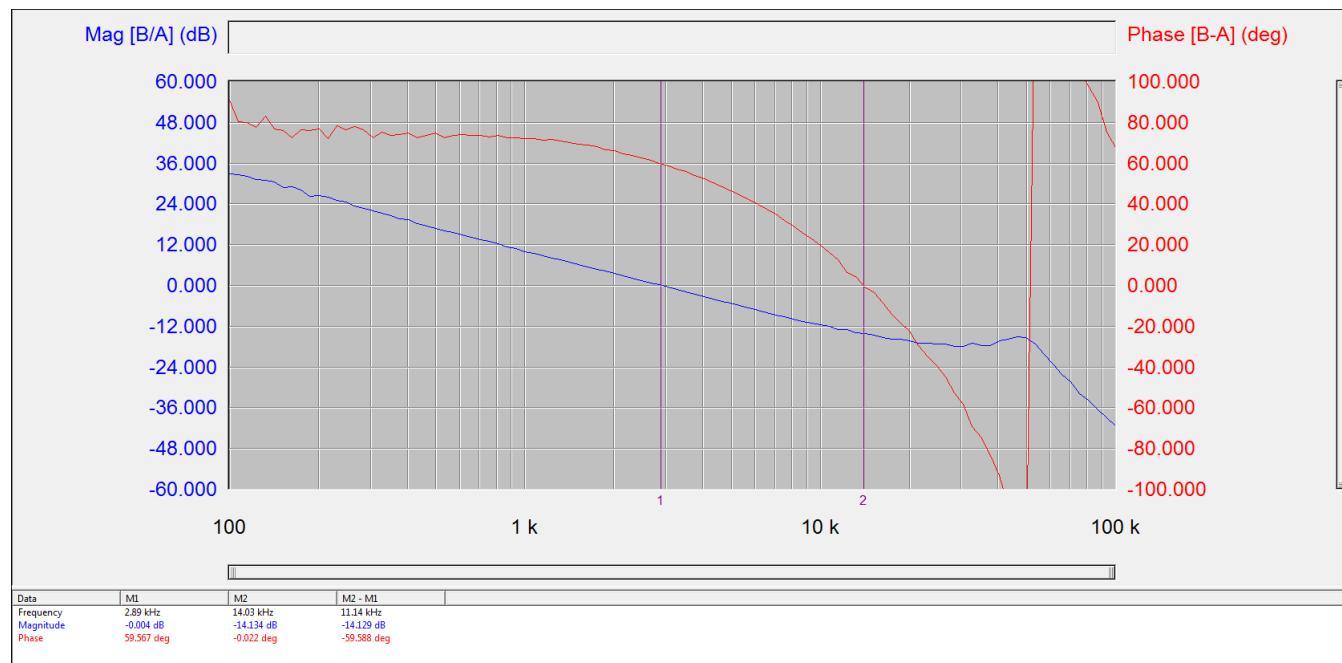


图 47. 16-V Input, 40-V Output, 10-A Load: 59.57-Degree Phase Margin, -14.13-dB Gain Margin

4 Design Files

4.1 Schematics

To download the schematics, see the design files at [TIDA-01610](#).

4.2 Bill of Materials

To download the bill of materials (BOM), see the design files at [TIDA-01610](#).

4.3 PCB Layout Recommendations

The PCB is a four-layer board with routing on all four layers. All components are placed on the top layer. The input caps, current sense resistors R2 and R23, inductors L1 and L2, the synchronous rectifier transistors, and the output capacitors are placed so that the copper traces are as short as possible and the current loop from the input capacitor ground to the output capacitor ground is short. Multiple large vias are used to ensure low impedance where high current nets change layers on the PCB. The switch transistors also form a short path from the input inductor to ground between the input and output capacitors. Because the LM25122-Q1 boost controllers are not in the high current path, they are placed away from the main current loop. All high current paths have large copper areas to minimize impedance. V_{OUT} is connected to the output filter on this layer.

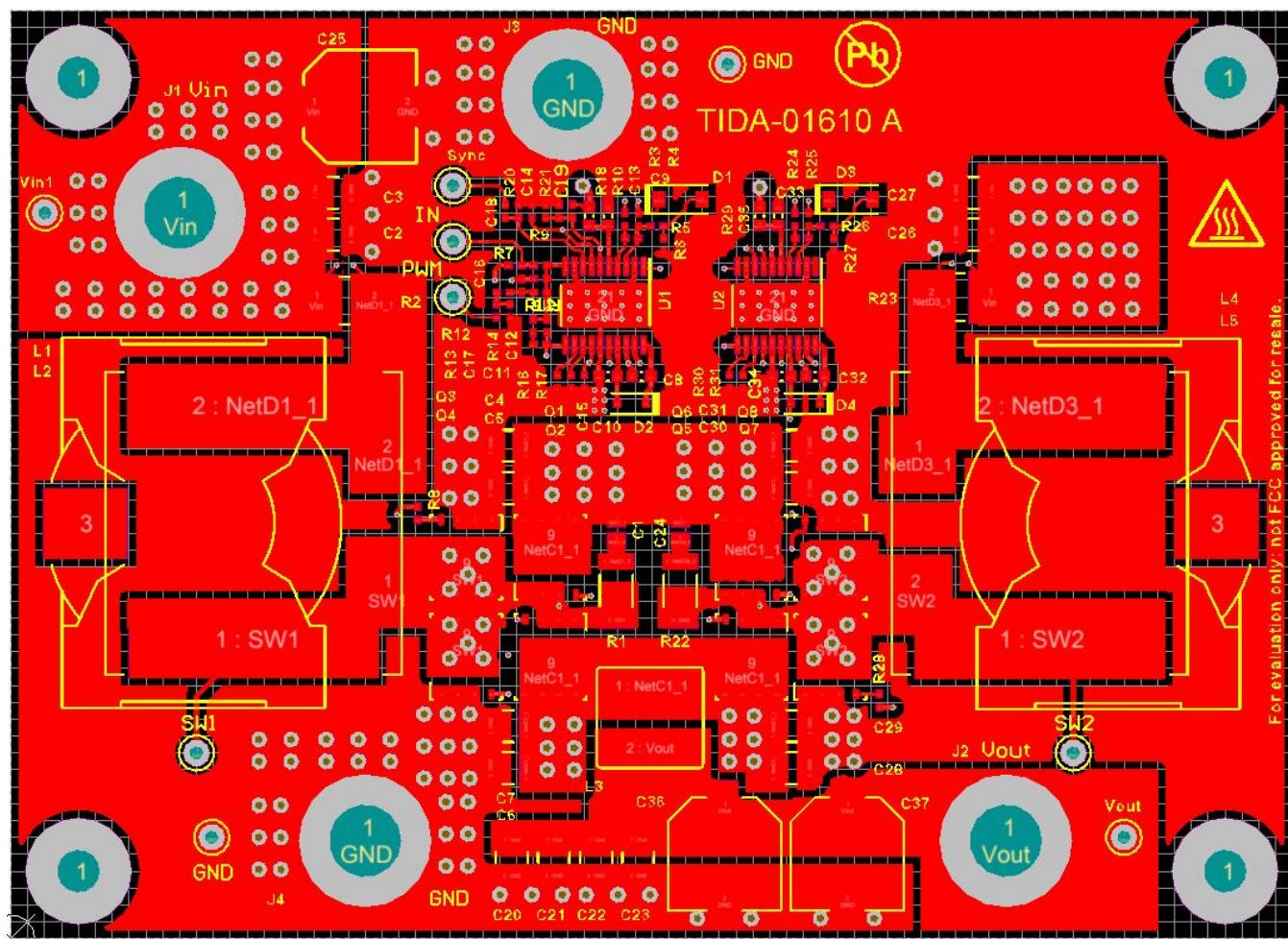


图 48. PCB Top Layer

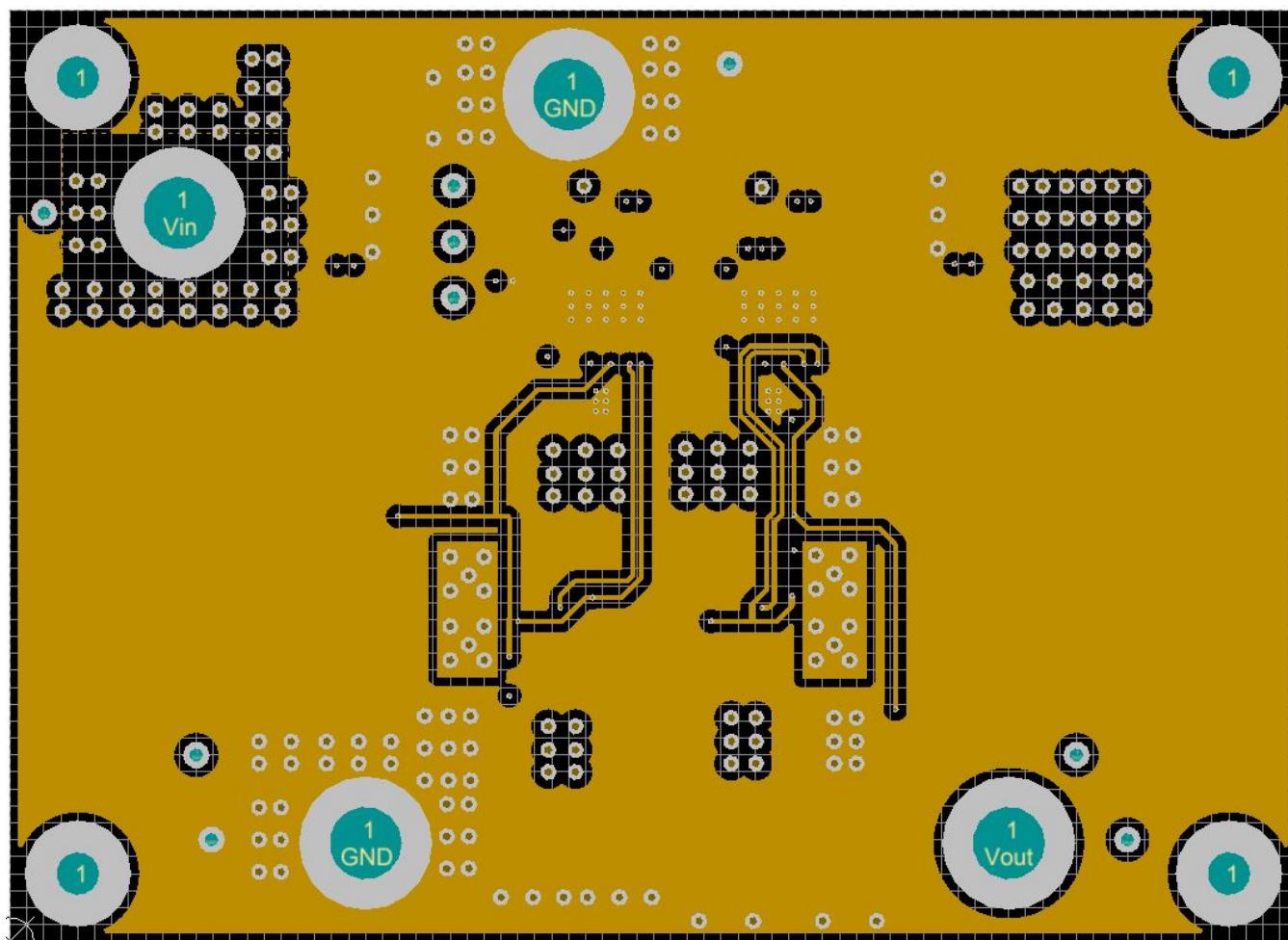


图 49. PCB Layer 2

On layer 2, HO1 is routed next to the part of SW1 that connects from U1 to Q1 and Q2, and HO2 and SW2 are routed in a similar manner from U2 to Q5 and Q6. LO1 and LO 2 are also routed on this layer. The large copper pour on this layer is ground.

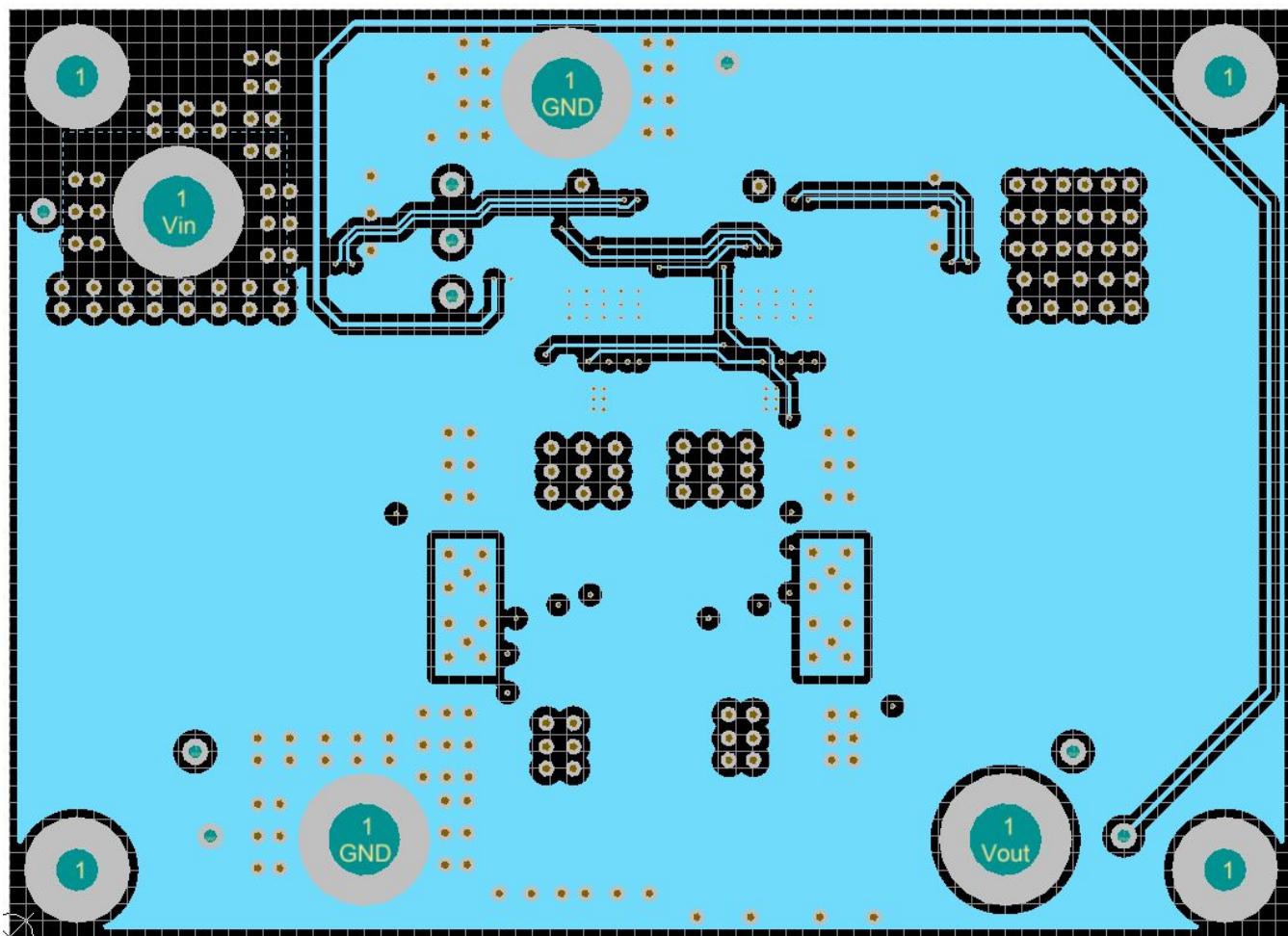


图 50. PCB Layer 3

PCB layer 3 contains the signals shared by U1 and U2. The pairs of nets toward the top are the Kelvin connections from current sense resistors R2 and R23. One connection in each pair is connected to V_{IN} . The vias for these connections fall inside of a V_{IN} plane that is on the bottom layer. Because of this, cutouts are placed around the four vias so that they do not connect to the plane. If they did, the current measurement would not be accurate due to the voltage not being sensed right at the resistors. Most of layer 3 is ground. The bottom has a plane for V_{IN} , a plane for net C1-1 (which is the connection point of the two output phases), and a ground plane.

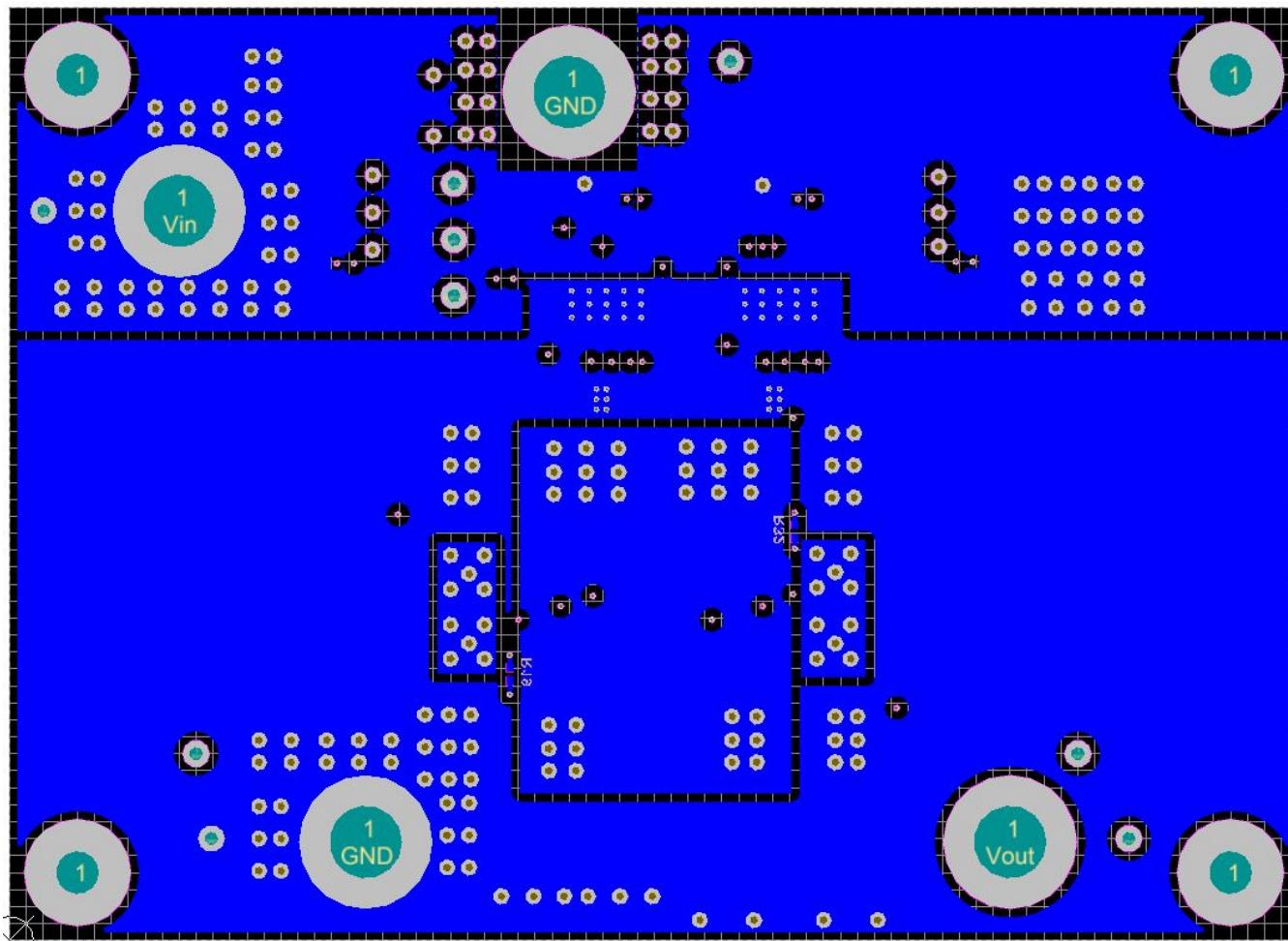


图 51. PCB Bottom Layer

4.3.1 Layout Prints

To download the layer plots, see the design files at [TIDA-01610](#).

4.4 Altium Project Files

To download the Altium project files, see the design files at [TIDA-01610](#).

4.5 Gerber Files

To download the Gerber files, see the design files at [TIDA-01610](#).

4.6 Assembly Drawings

To download the assembly drawings, see the design files at [TIDA-01610](#).

5 商标

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

6 About the Authors

MARK KNAPP is a systems architect at Texas Instruments Incorporated who specializes in automotive premium audio systems and instrument clusters. He also has an extensive background in video camera systems and infrared imaging systems for military, automotive, and industrial applications. Mark earned his BSEE at the University of Michigan-Dearborn and his MSEE at the University of Texas at Dallas.

XINYU DAI has a system application role at Texas Instruments Incorporated and specializes in designing various power supply topologies for industrial, consumer, and automotive applications. His background includes kilowatt multi-phase designs, compact designs for personal electronics, and EMI optimized designs for automotive applications. Xinyu earned his BSEE at the Georgia Institute of Technology with high honor.

有关 TI 设计信息和资源的重要通知

德州仪器 (TI) 公司提供的技术、应用或其他设计建议、服务或信息，包括但不限于与评估模块有关的参考设计和材料（总称“TI 资源”），旨在帮助设计人员开发整合了 TI 产品的应用；如果您（个人，或如果是代表贵公司，则为贵公司）以任何方式下载、访问或使用了任何特定的 TI 资源，即表示贵方同意仅为该等目标，按照本通知的条款进行使用。

TI 所提供的 TI 资源，并未扩大或以其他方式修改 TI 对 TI 产品的公开适用的质保及质保免责声明；也未导致 TI 承担任何额外的义务或责任。TI 有权对其 TI 资源进行纠正、增强、改进和其他修改。

您理解并同意，在设计应用时应自行实施独立的分析、评价和判断，且应全权负责并确保应用的安全性，以及您的应用（包括应用中使用的所有 TI 产品）应符合所有适用的法律法规及其他相关要求。你就您的应用声明，您具备制订和实施下列保障措施所需的一切必要专业知识，能够（1）预见故障的危险后果，（2）监视故障及其后果，以及（3）降低可能导致危险的故障几率并采取适当措施。您同意，在使用或分发包含 TI 产品的任何应用前，您将彻底测试该等应用和该等应用所用 TI 产品的功能而设计。除特定 TI 资源的公开文档中明确列出的测试外，TI 未进行任何其他测试。

您只有在为开发包含该等 TI 资源所列 TI 产品的应用时，才被授权使用、复制和修改任何相关单项 TI 资源。但并未依据禁止反言原则或其他法理授予您任何 TI 知识产权的任何其他明示或默示的许可，也未授予您 TI 或第三方的任何技术或知识产权的许可，该等产权包括但不限于任何专利权、版权、屏蔽作品权或与使用 TI 产品或服务的任何整合、机器制作、流程相关的其他知识产权。涉及或参考了第三方产品或服务的信息不构成使用此类产品或服务的许可或与其相关的保证或认可。使用 TI 资源可能需要您向第三方获得对该等第三方专利或其他知识产权的许可。

TI 资源系“按原样”提供。TI 兹免除对 TI 资源及其使用作出所有其他明确或默认的保证或陈述，包括但不限于对准确性或完整性、产权保证、无屡发故障保证，以及适销性、适合特定用途和不侵犯任何第三方知识产权的任何默认保证。

TI 不负责任何申索，包括但不限于因组合产品所致或与之有关的申索，也不为您辩护或赔偿，即使该等产品组合已列于 TI 资源或其他地方。对因 TI 资源或其使用引起或与之有关的任何实际的、直接的、特殊的、附带的、间接的、惩罚性的、偶发的、从属或惩戒性损害赔偿，不管 TI 是否获悉可能会产生上述损害赔偿，TI 概不负责。

您同意向 TI 及其代表全额赔偿因您不遵守本通知条款和条件而引起的任何损害、费用、损失和/或责任。

本通知适用于 TI 资源。另有其他条款适用于某些类型的材料、TI 产品和服务的使用和采购。这些条款包括但不限于适用于 TI 的半导体产品 (<http://www.ti.com/sc/docs/stdterms.htm>)、**评估模块** 和样品 (<http://www.ti.com/sc/docs/samptersms.htm>) 的标准条款。

邮寄地址：上海市浦东新区世纪大道 1568 号中建大厦 32 楼，邮政编码：200122
Copyright © 2018 德州仪器半导体技术（上海）有限公司